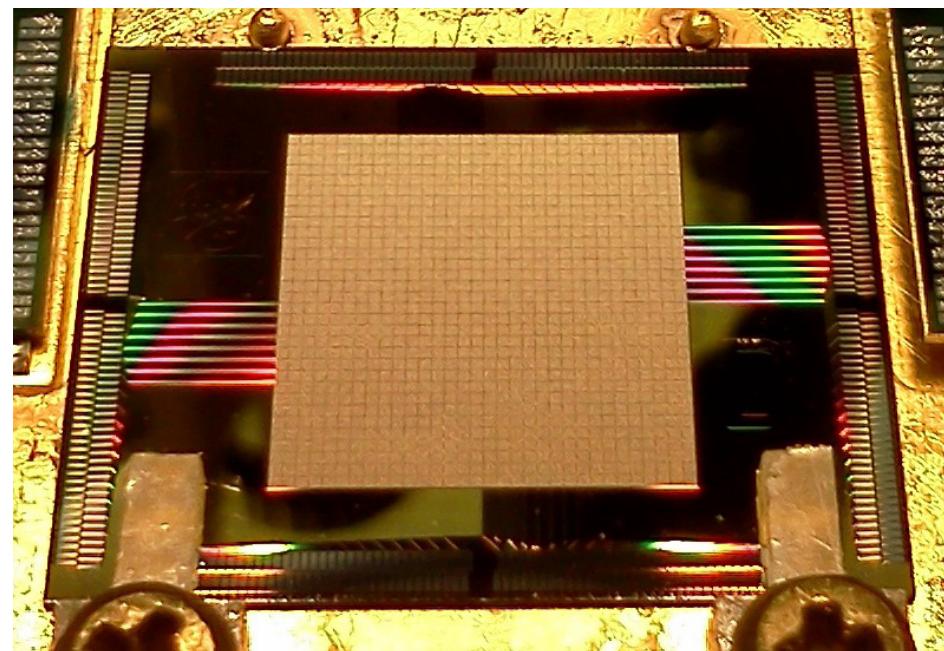
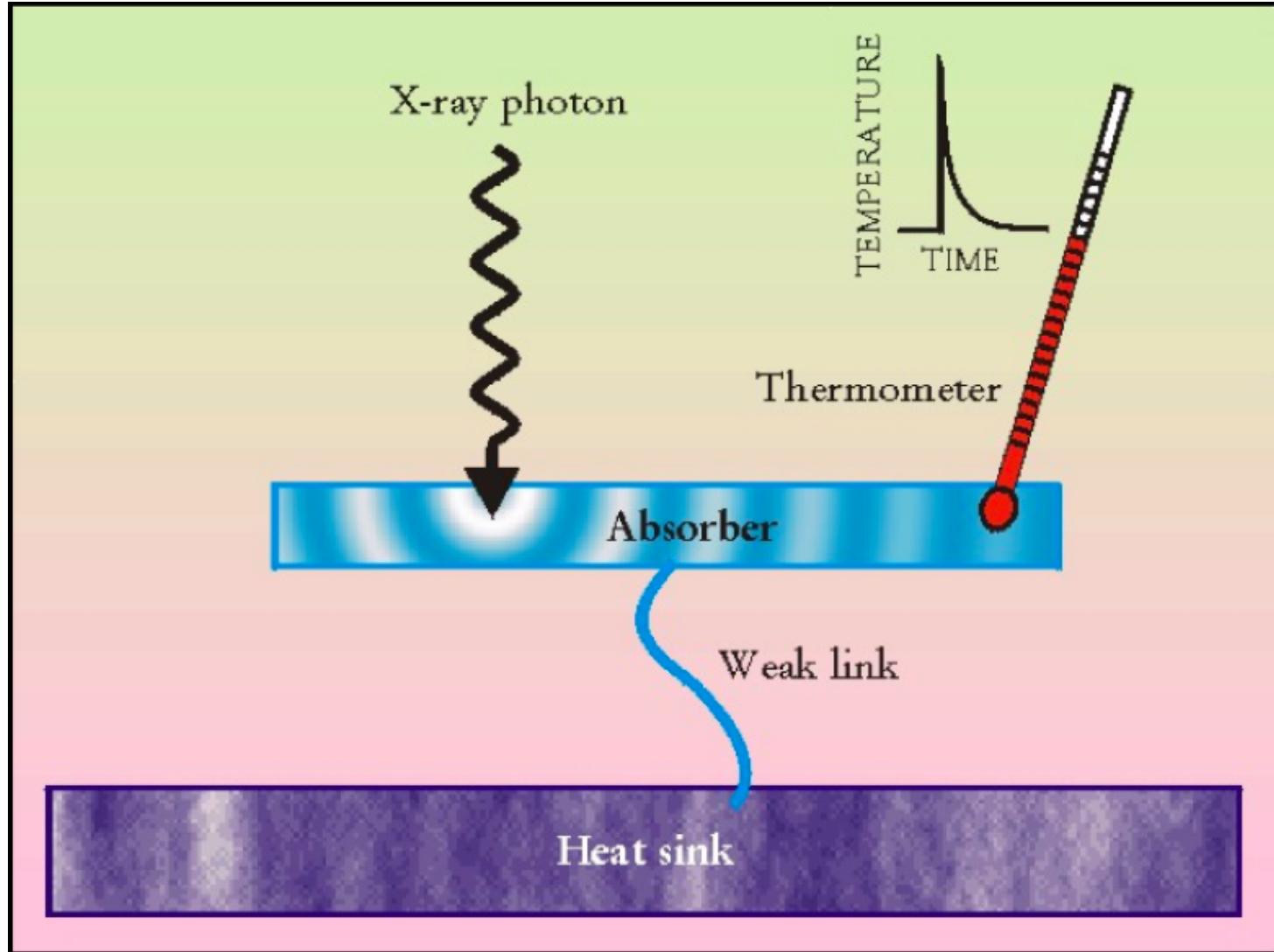


Status of current efforts and future needs in detectors

Simon Bandler: X-ray Astrophysics Laboratory at NASA/GSFC

- Sensor technologies – the good and the bad
- Who's doing what ?
- State-of-the-art performance
- XMS instrument concepts
- Array size limits
- Getting to TRL-6





$$\delta T = \frac{E}{C_{\text{tot}}}$$

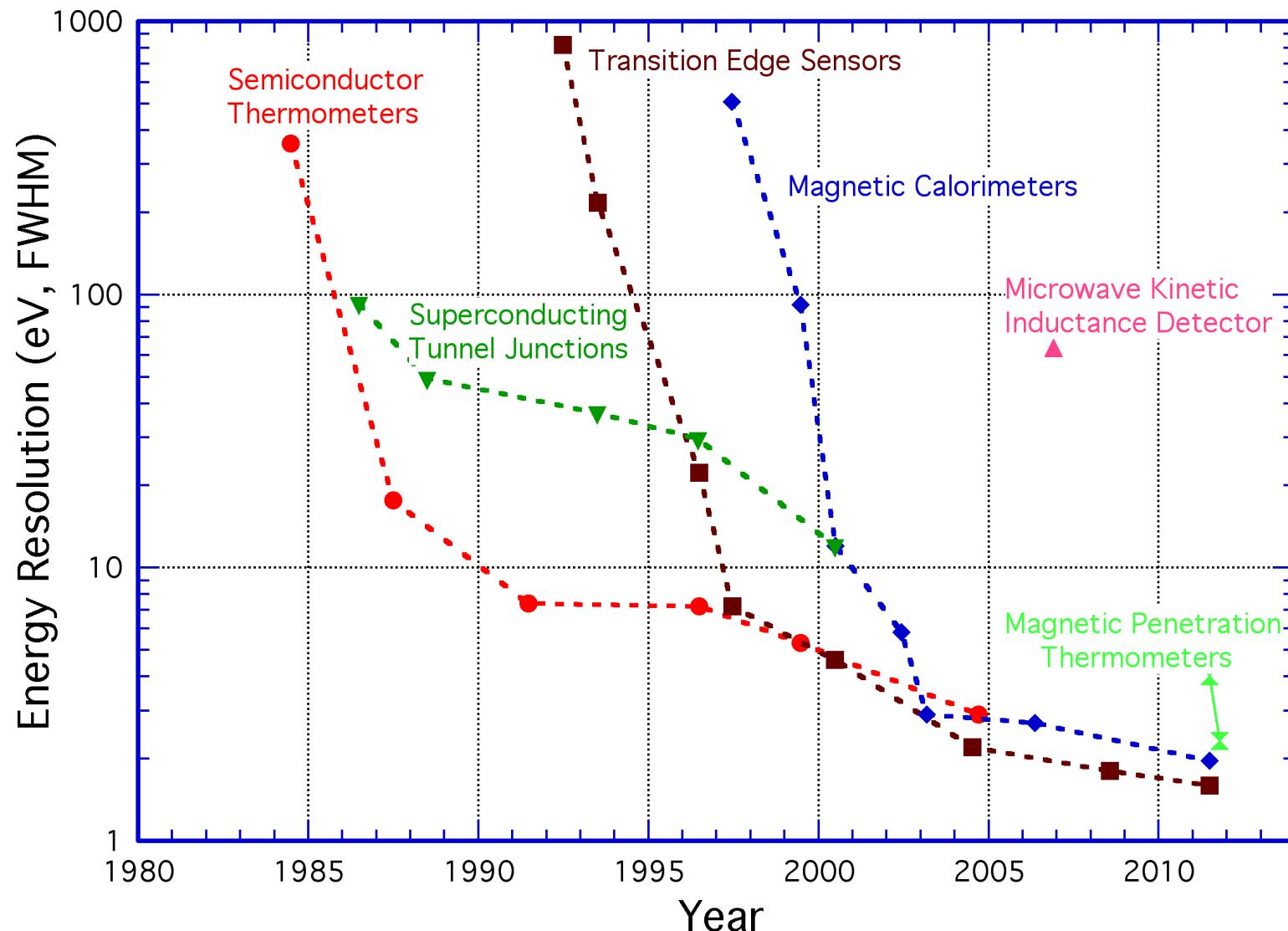
Thermal relaxation time:

$$\tau = \frac{C_{\text{tot}}}{G}$$

Thermal conductance

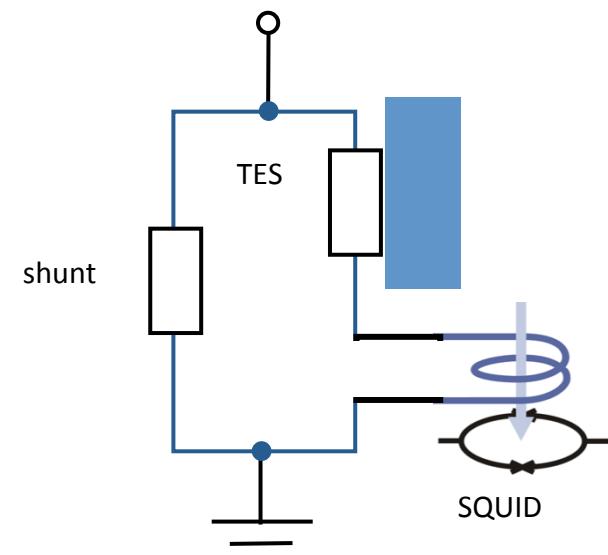
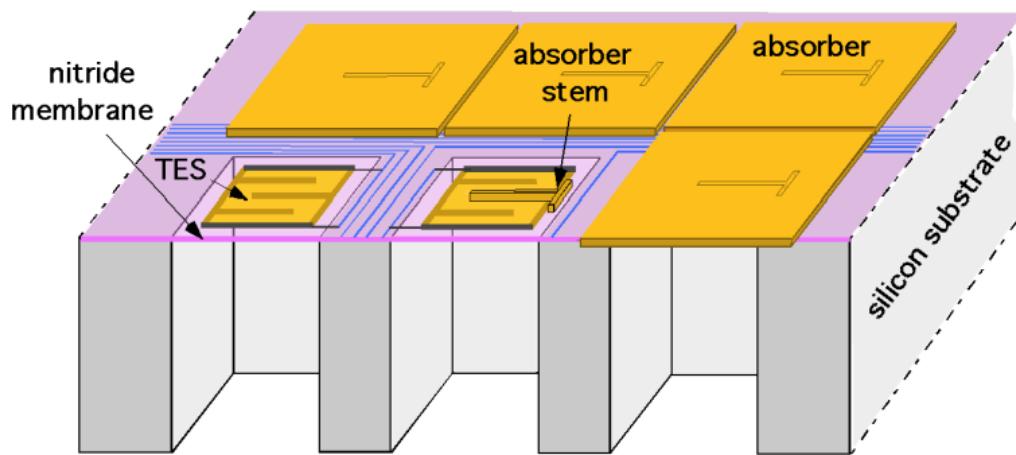
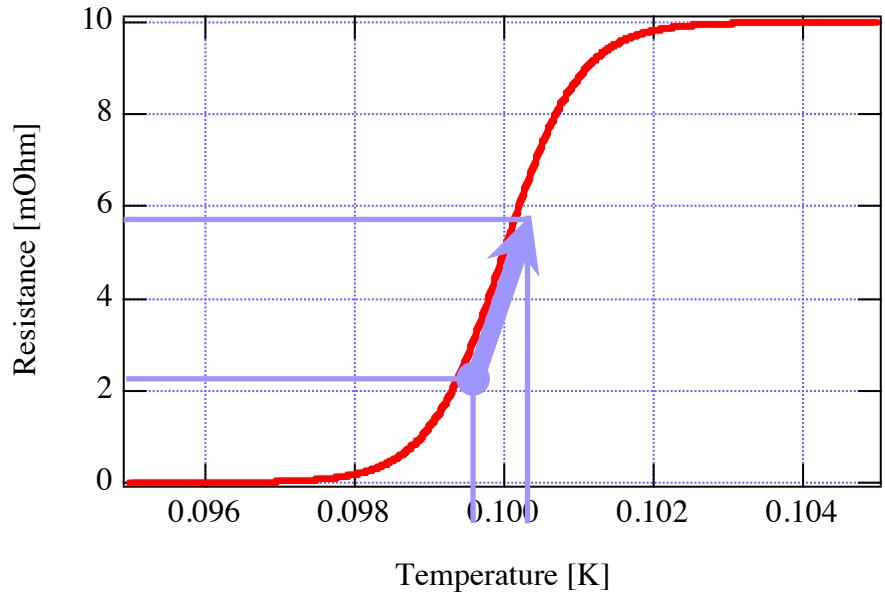
X-ray microcalorimeters capable of 1 eV energy resolution

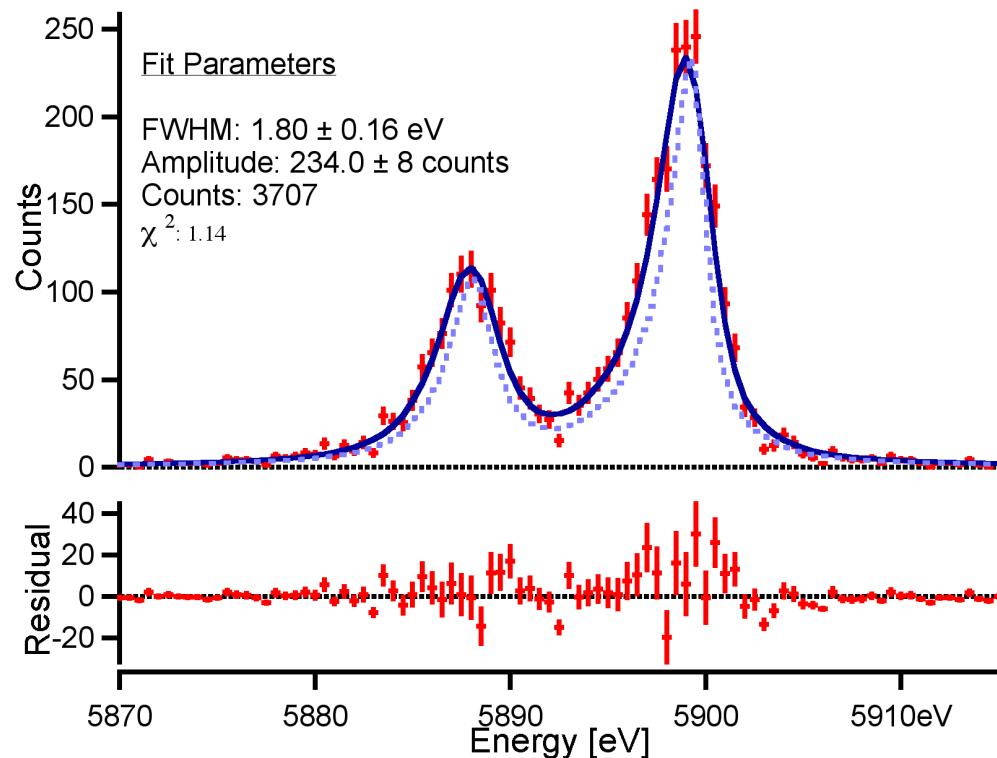
S.H. Moseley, J.C. Mather, D. McCammon, J. Appl. Phys. 56, 1257 (1984)



Transition-edge Sensors

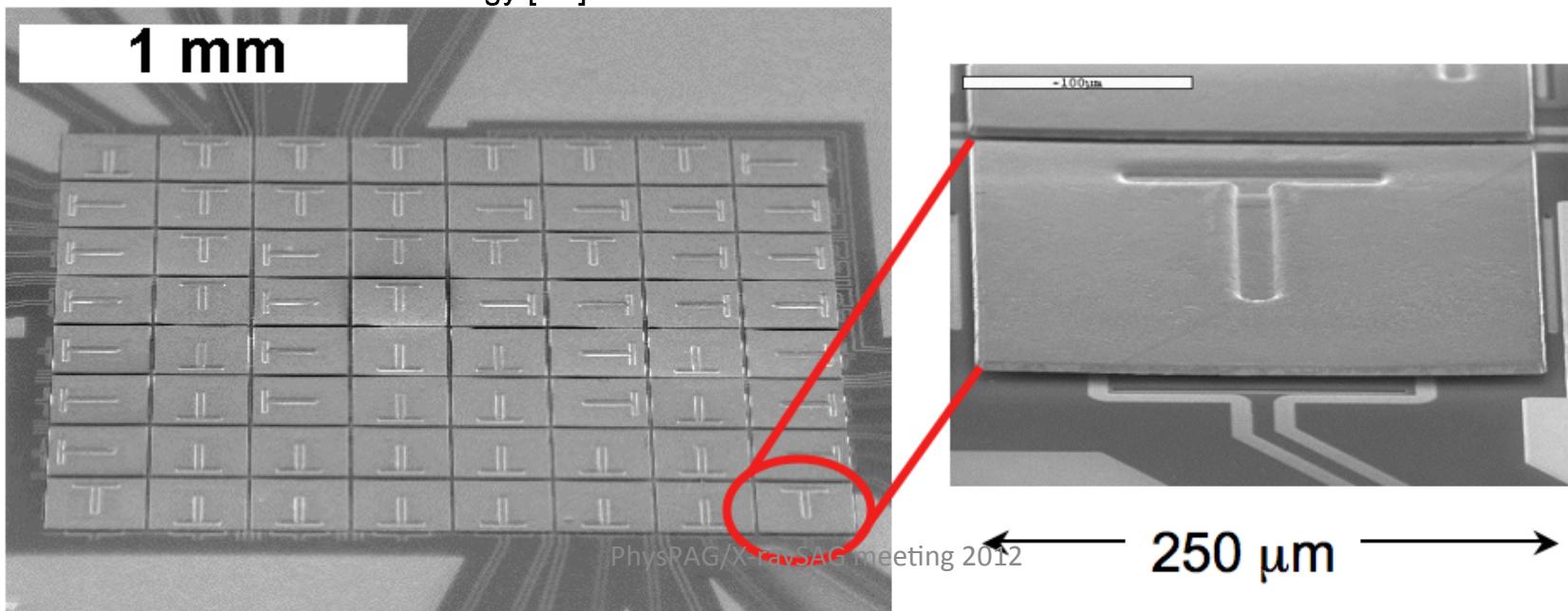
- Superconductor biased in its transition
- Low resistance allows read out with SQUIDs
- $T_c = 0.1 \text{ K}$
- Overhanging absorbers are several microns thick





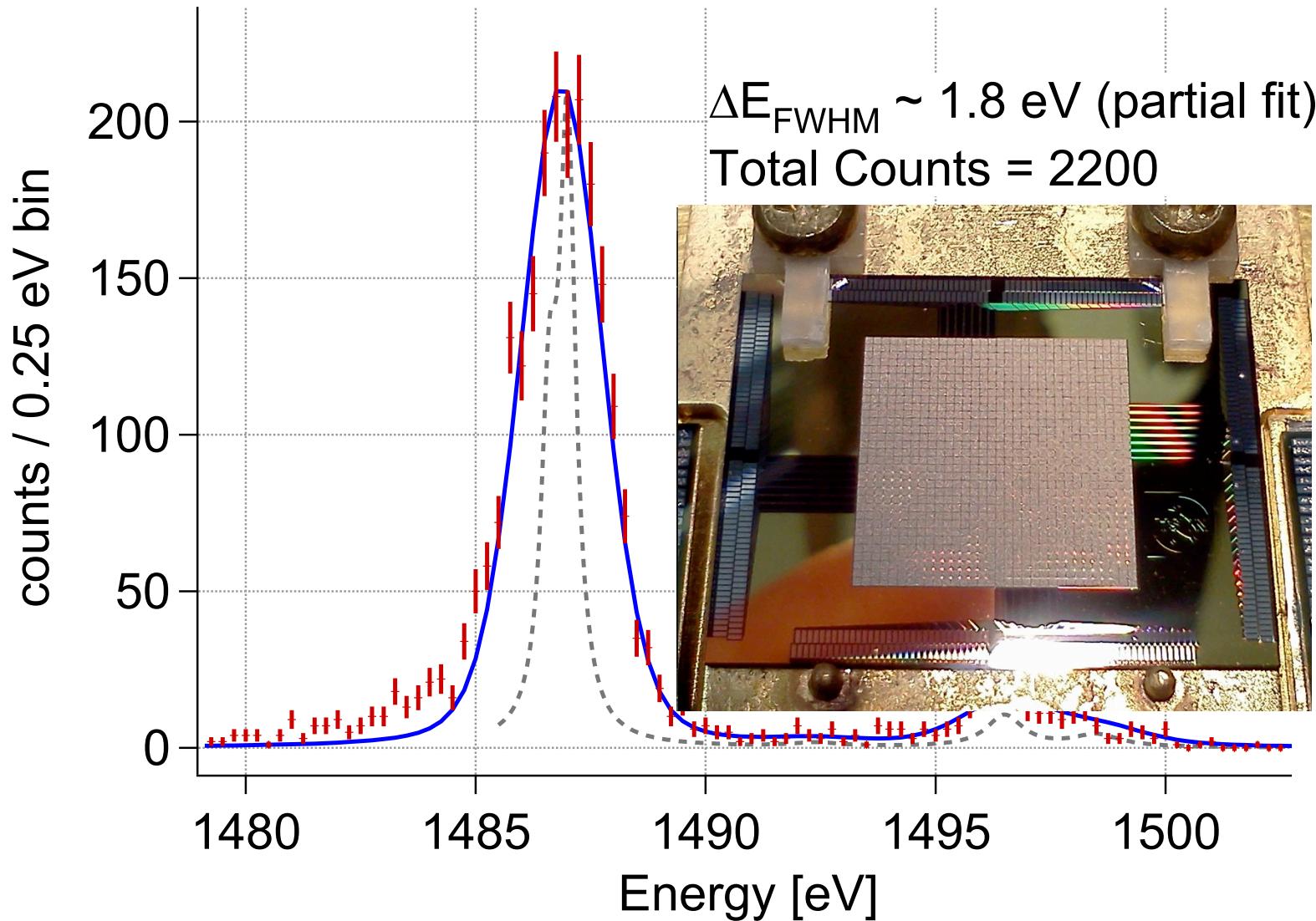
- Mn $K\alpha_1$ & $K\alpha_2$ x-rays at 6 keV from an ^{55}Fe internal conversion source
- Instrumental broadening consistent with a gaussian response with 1.8 eV resolution FWHM

Array absorbers :
 $240 \mu\text{m} \times 240 \mu\text{m}$
 $0.7 \mu\text{m}$ Au & $6 \mu\text{m}$ Bi



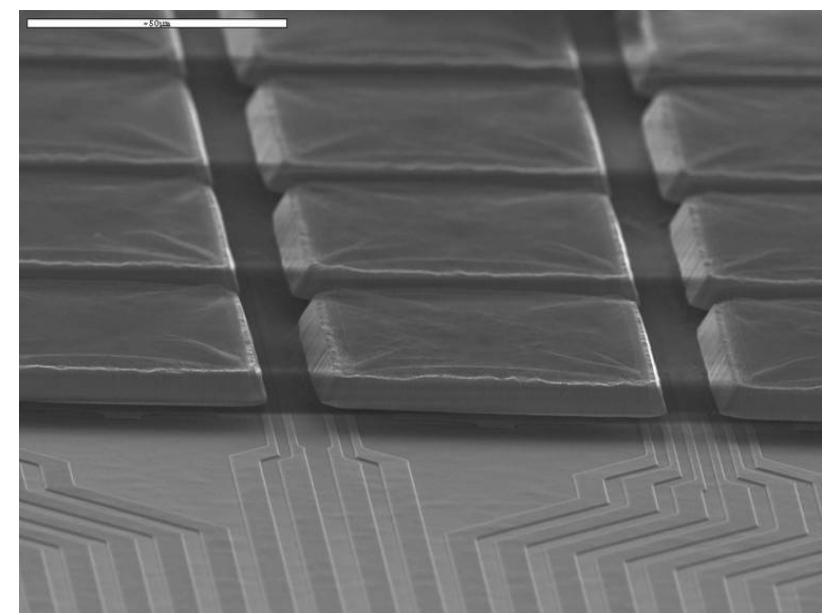
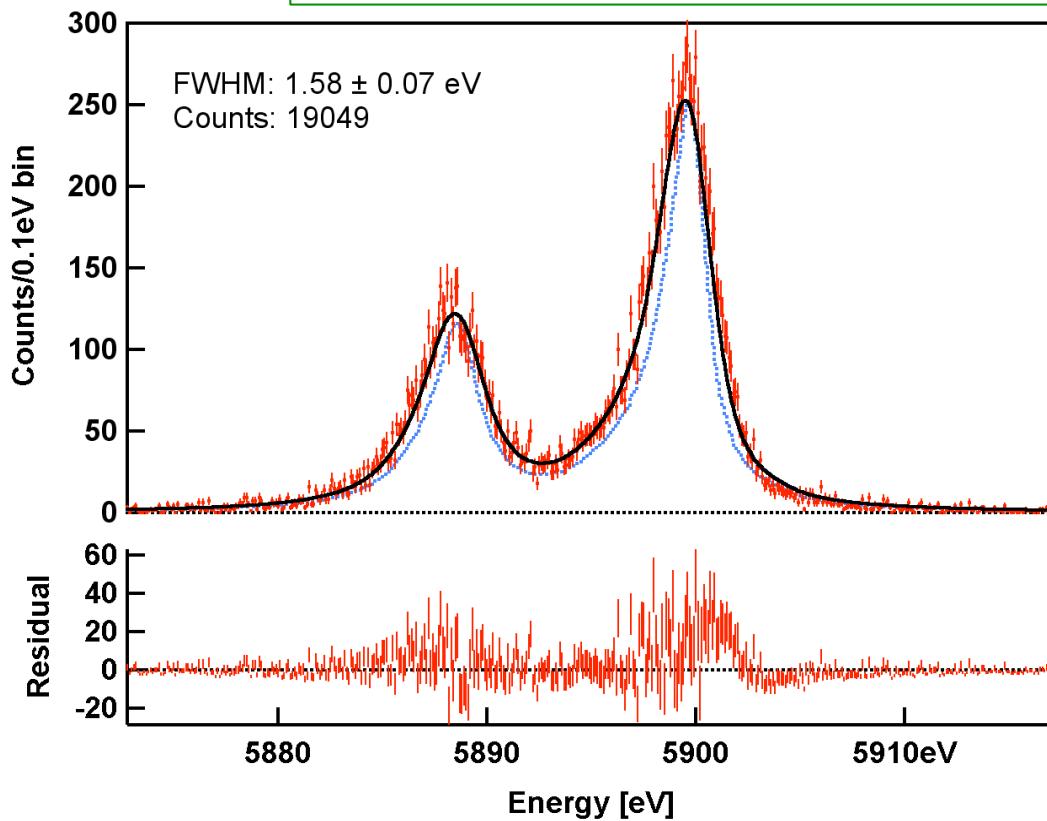
Current state-of-the-art

32 x 32 array with
300 micron pixels

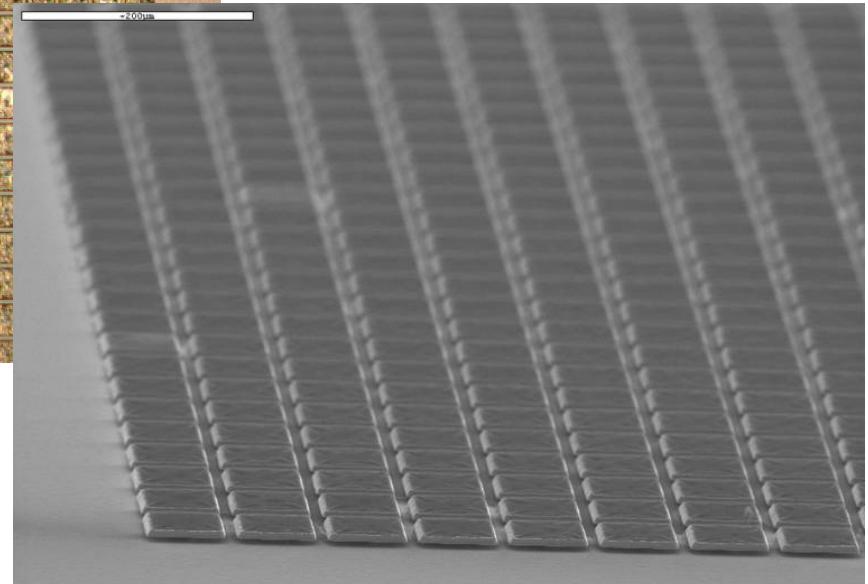
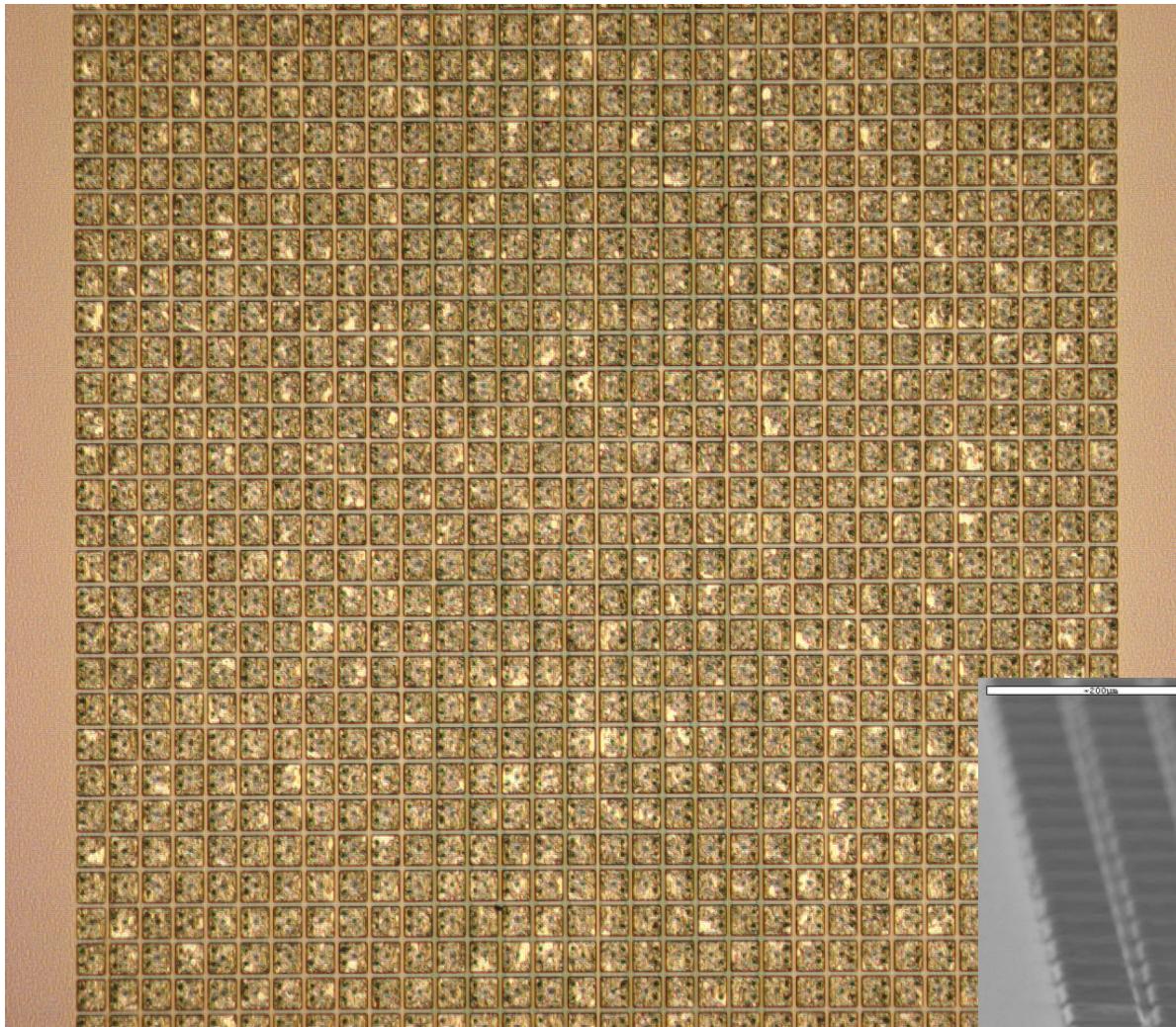


TES – smaller pixels

- Suited to shorter focal lengths and/or higher spatial resolution
- Fantastic microcalorimeter energy resolution
- Use of all-gold absorbers - great for reliable fast thermalization
- Solid substrate design - great for heat-sinking/low cross-talk
- Use of multiple designs on a single silicon chip
 - no variation in back-etching / fabrication
 - less complex focal plane assembly design
- Through choice of T_c , can be optimized for speed or resolution.



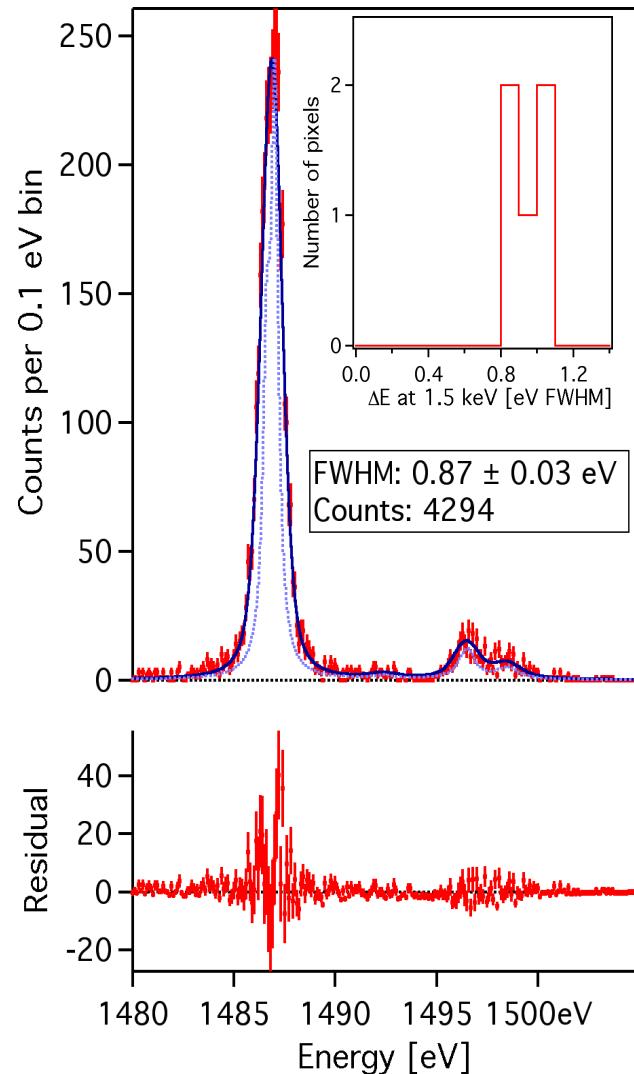
57 μm pixel with 30 μs time constant



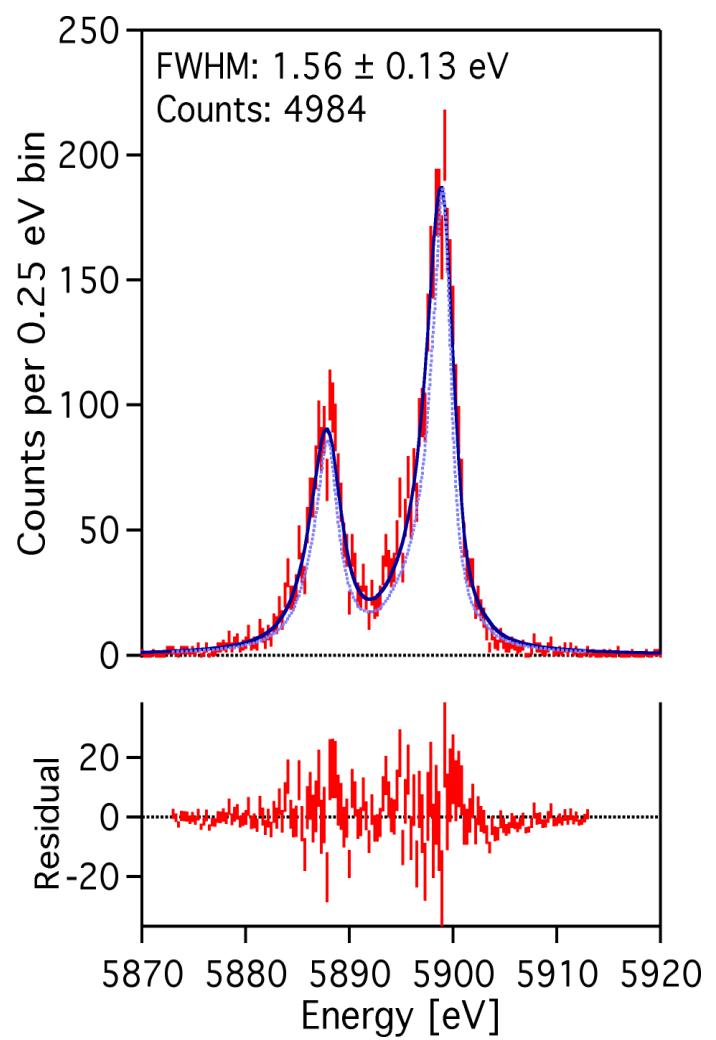
Motivated by solar
physics applications:

- 32x32 arrays
- TES on 75 μm pitch
- Absorber gold:
 $65\mu\text{m} \times 65\mu\text{m} \times 4.0\mu\text{m}$

$\Delta E \sim 0.9$ eV (FWHM) at 1.5 keV (Al-K)



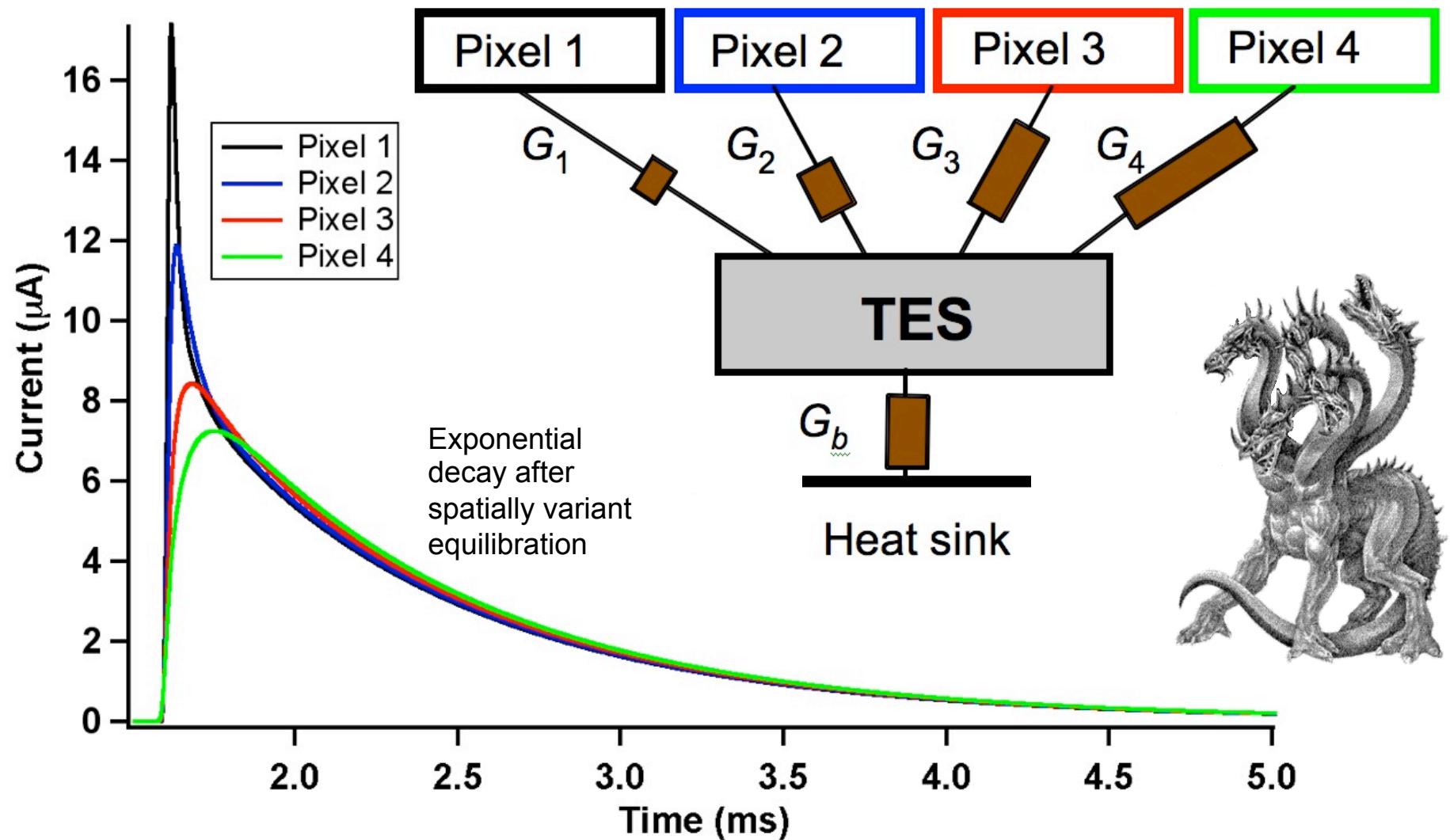
$\Delta E \sim 1.6$ eV (FWHM) at 6 keV (Mn-K)



- Surpasses previous best at 1.5 keV
- Low T_c pixel results match best resolution at 6 keV (utilizing non-stationary noise analysis)
- Count rate capability of a few 10's per second

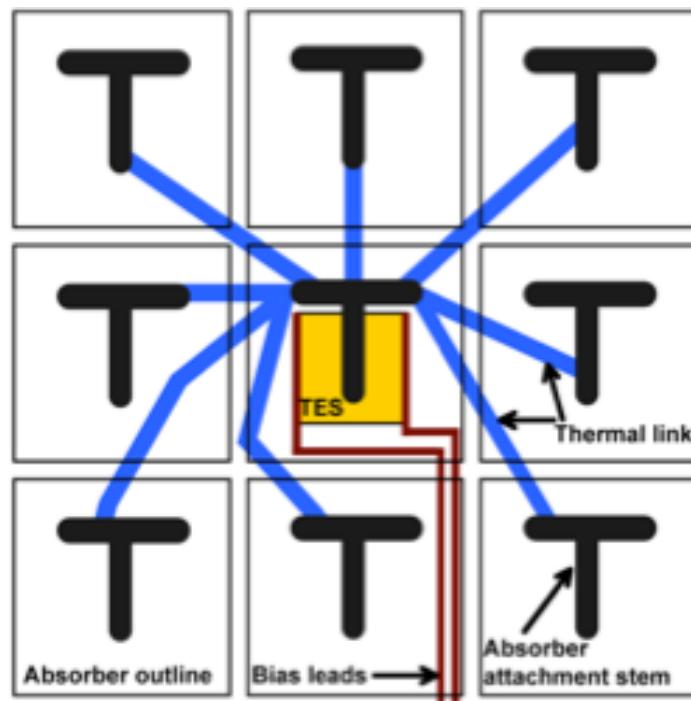
Multi Absorber TES “Hydras” - 1 TES, 4 absorbers

– increase field of view for a fixed number of read-out channels

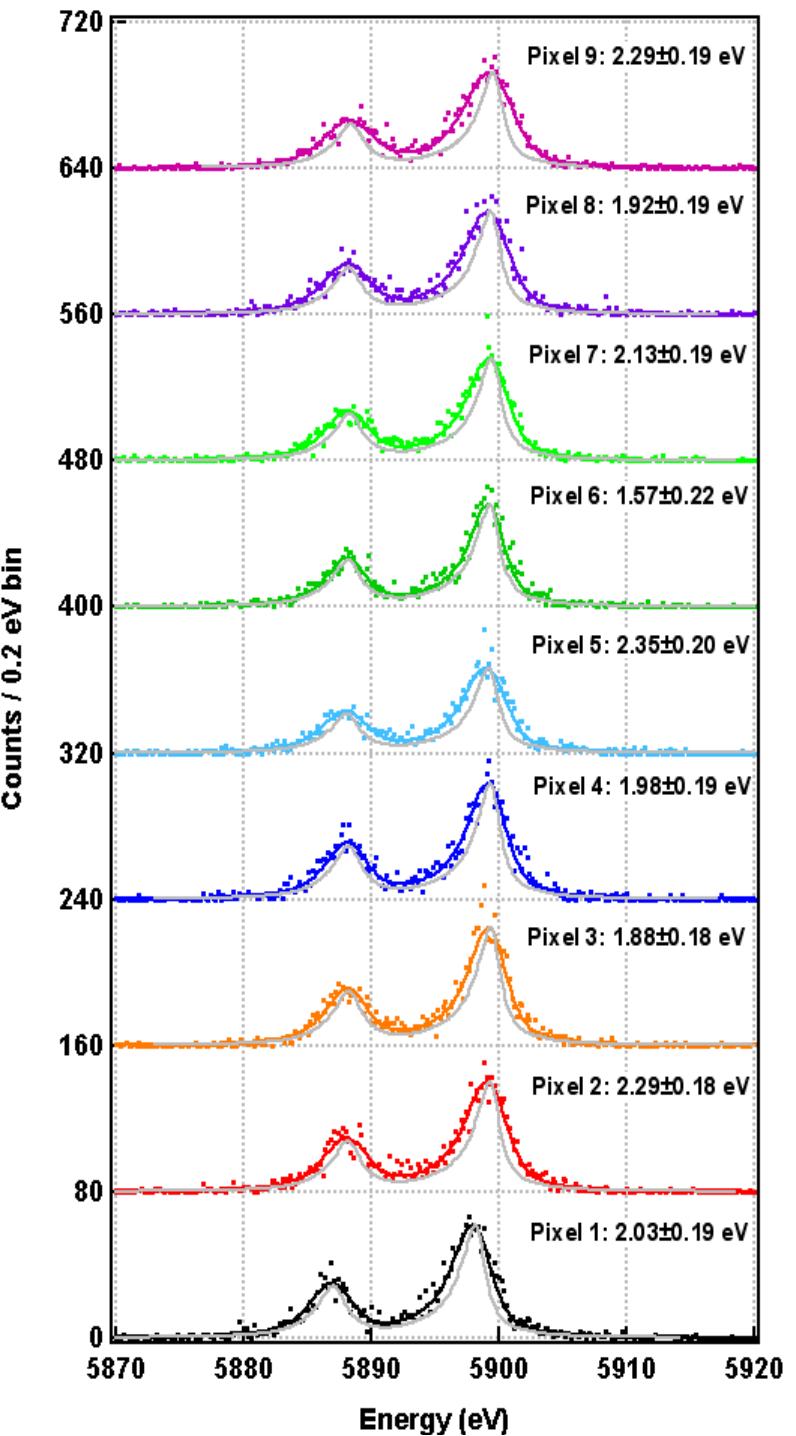


Small Hydra Detectors

- Close-packed 2x2 and 3x3 Hydras tested
- n absorbers $\Rightarrow \Delta E_{\text{Hydra}} \sim n^{1/2} \Delta E_{\text{Single Pixel}}$
 $\Delta E_{\text{Single Pixel}} \sim 0.7 \text{ eV}$
 $n = 4, \Delta E_{\text{Hydra}} \sim 1.4 \text{ eV}$
 $n = 9, \Delta E_{\text{Hydra}} \sim 2.1 \text{ eV}$
- 3x3 array of $65 \mu\text{m}$ absorbers, $5.0 \mu\text{m}$ thick.
- 2.2 eV - rms (FWHM) resolution at 6 keV !



PhysPAG/X-raySAG meeting



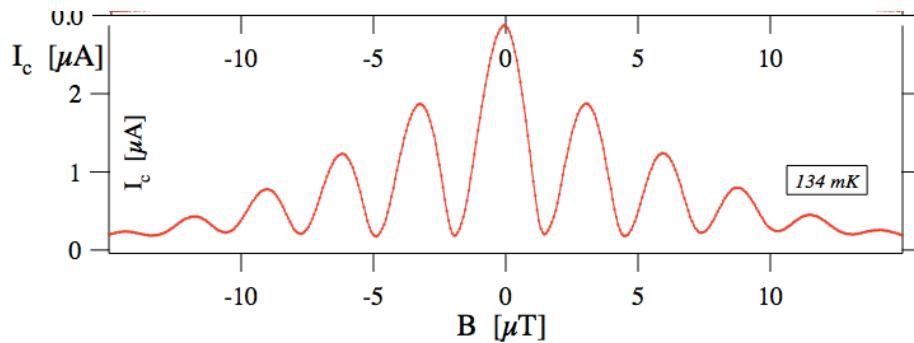
TES

The good:

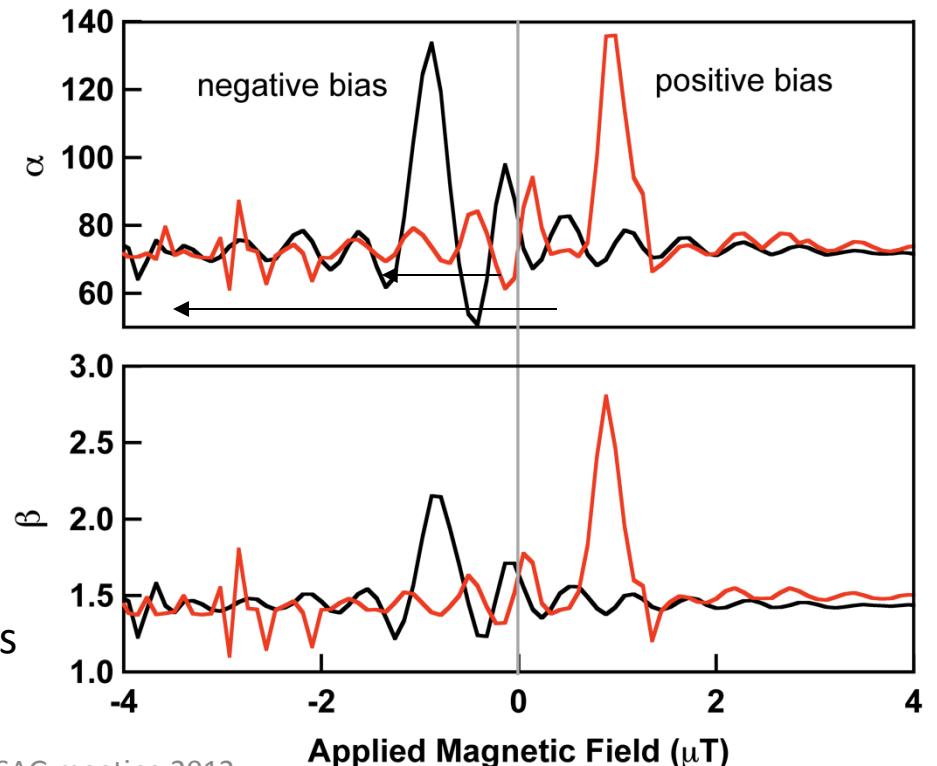
- Best documented energy resolution performance
- Highly multiplexable read-out (more later)
- Highest TRL of all technologies with kilo-pixel potential
- Large variety of pixel sizes possible

The bad:

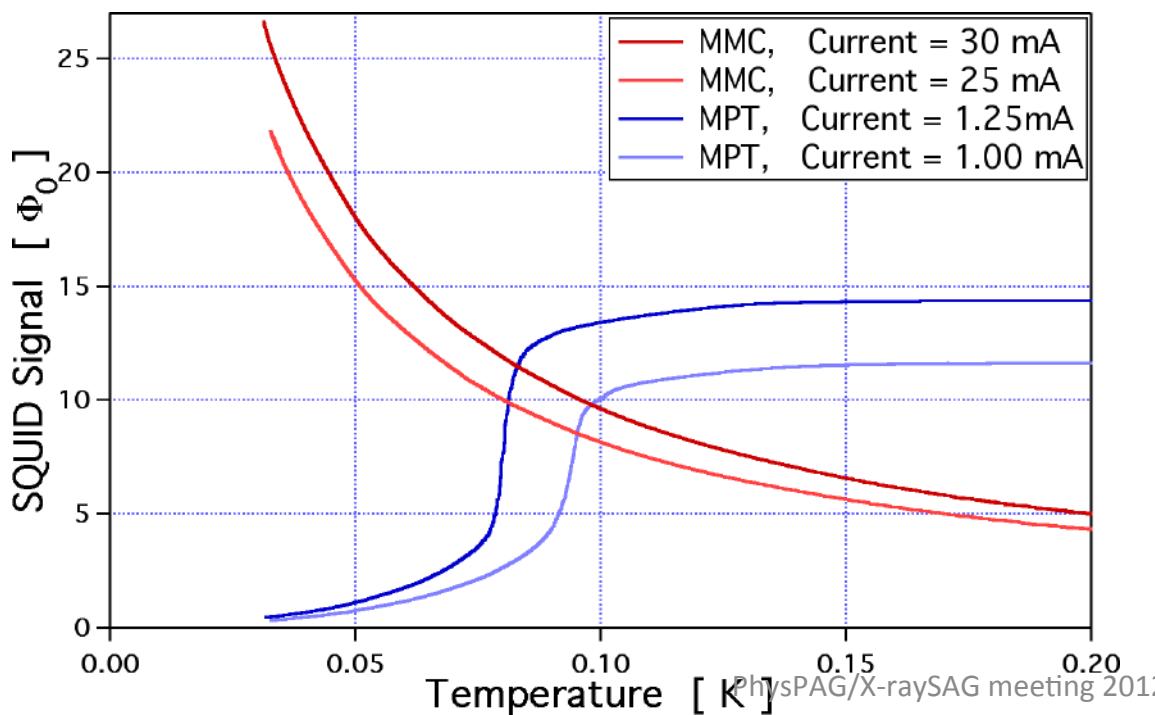
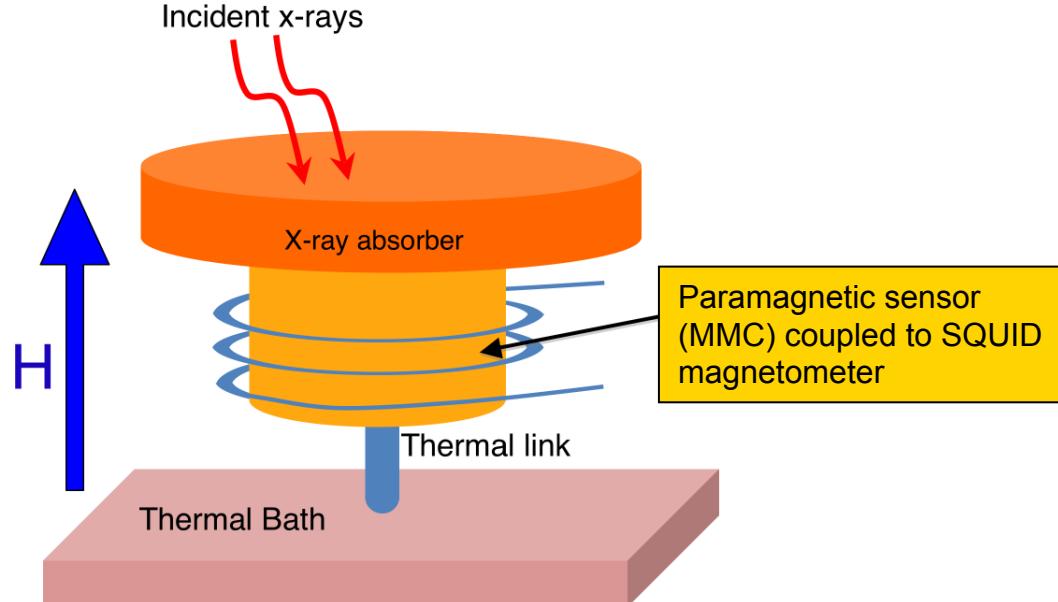
- Superconducting leads attached to TES produce long-range S-N-S junction
 - Very interesting physics – *J.E. Sadleir et al., PRL 104 4 (2010) 0470032010, Phys. Rev. B. 84 (2011) 184502*
 - But high sensitivity to magnetic fields -> some non-uniformity and design complications



Junction-like Fraunhofer pattern in $I_c(B)$
=> Variations in signal size and noise under bias



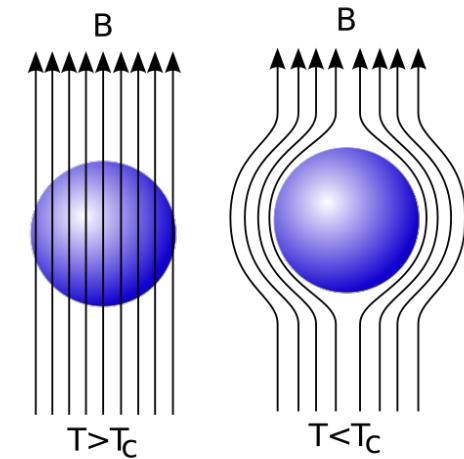
Magnetic Calorimeters (MMC) & Magnetic Penetration Thermometer (MPT) Microcalorimeters



Paramagnetic sensor: Au:Er

$$M \propto \frac{1}{T}$$

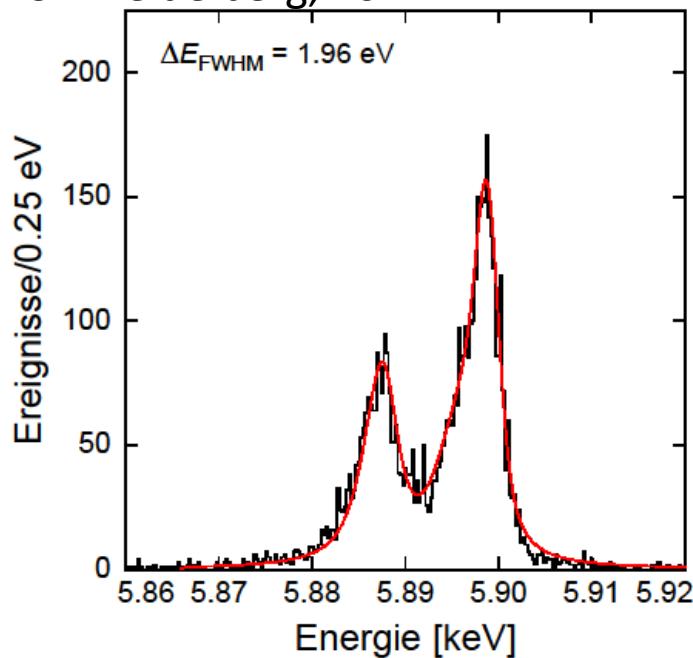
$$\delta M = \frac{\partial M}{\partial T} \delta T = \frac{\partial M}{\partial T} \frac{\delta E}{C}$$



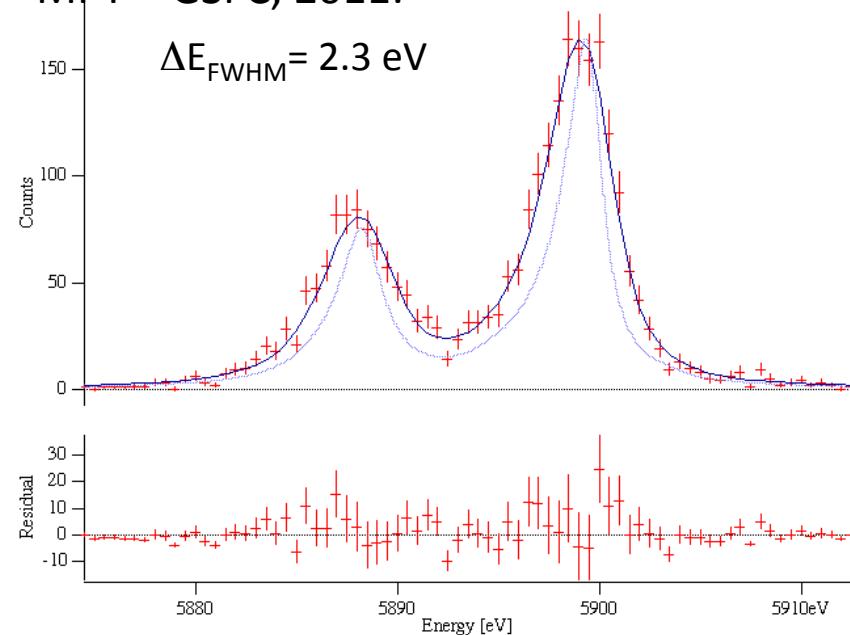
no heat dissipated in the sensor
no galvanic contact to the sensor

Best magnetically coupled calorimeter results at 6 keV:

MMC – Heidelberg, 2011:



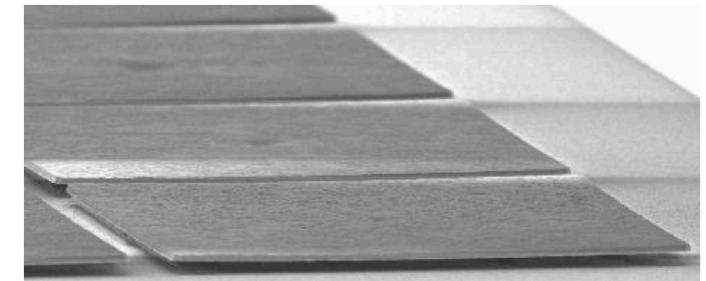
MPT – GSFC, 2011:



MMC / MPT

The good:

- Potential for the very highest energy resolution
(no Johnson noise)
- Non-dissipative nature => larger array sizes might be possible
- Can be directly connected to metallic heat sink – reduction of thermal crosstalk

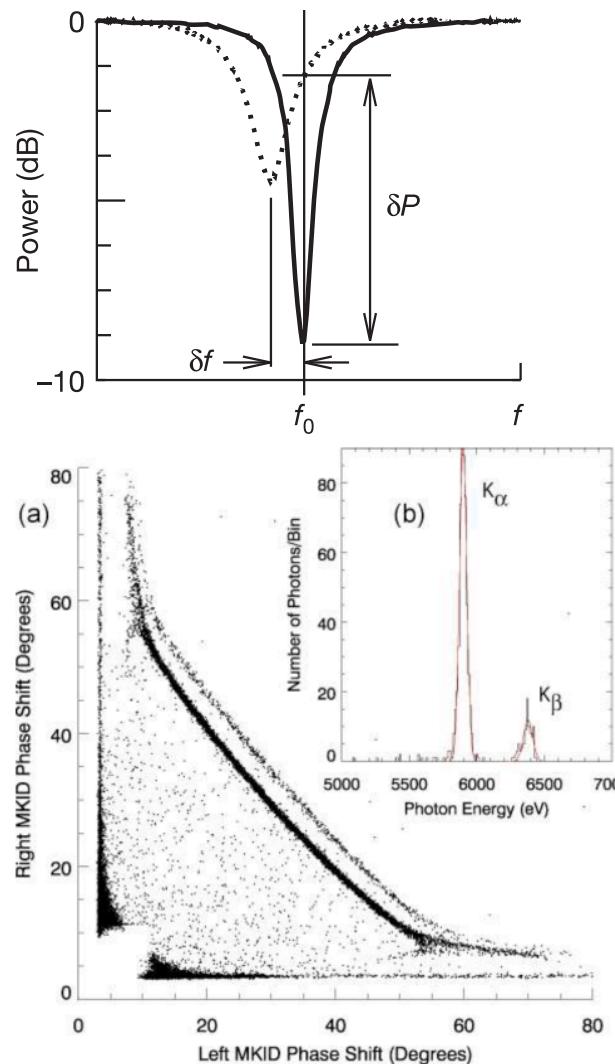
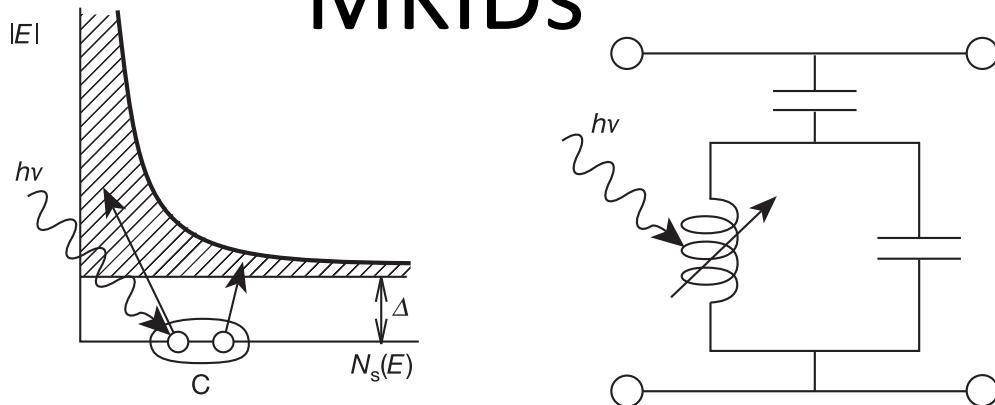


*250 μm absorb., 2.8 μm thick Au,
supported on single 3.5 μm stems*

The bad:

- Hardest to technology to read out and multiplex

MKIDs



The good:

- Potentially the easiest technology to multiplex with microwave read-out
- Investment taking place in infrared bolometer community (JPL)

The bad:

- High energy resolution is very difficult, especially at 6 keV
- Read-out needs development of parametric amplifiers
- Read-out electronics a long way from being flight qualified – no near-term alternative
- Superconducting absorbers are difficult

Best results achieved using position-sensitive MKIDs ~ 60 eV at 6 keV.

Ongoing programs:

ROSES-APRA supported basic research programs:

- GSFC TES development (Kilbourne)
- NIST SQUID read-out and detector development (Irwin)
- Brown/UMD/GSFC MMC/MPT development (Bandler)
- Santa Barbara (supported by JPL) – MKID (Mazin)
- Wisconsin/GSFC - rocket application, XQC, filters - soft x-rays (McCammon)
- MIT/GSFC/NIST - rocket development, uX, - focused x-rays (Figueroa)

IXO directed funding, ROSES-SAT funding ?

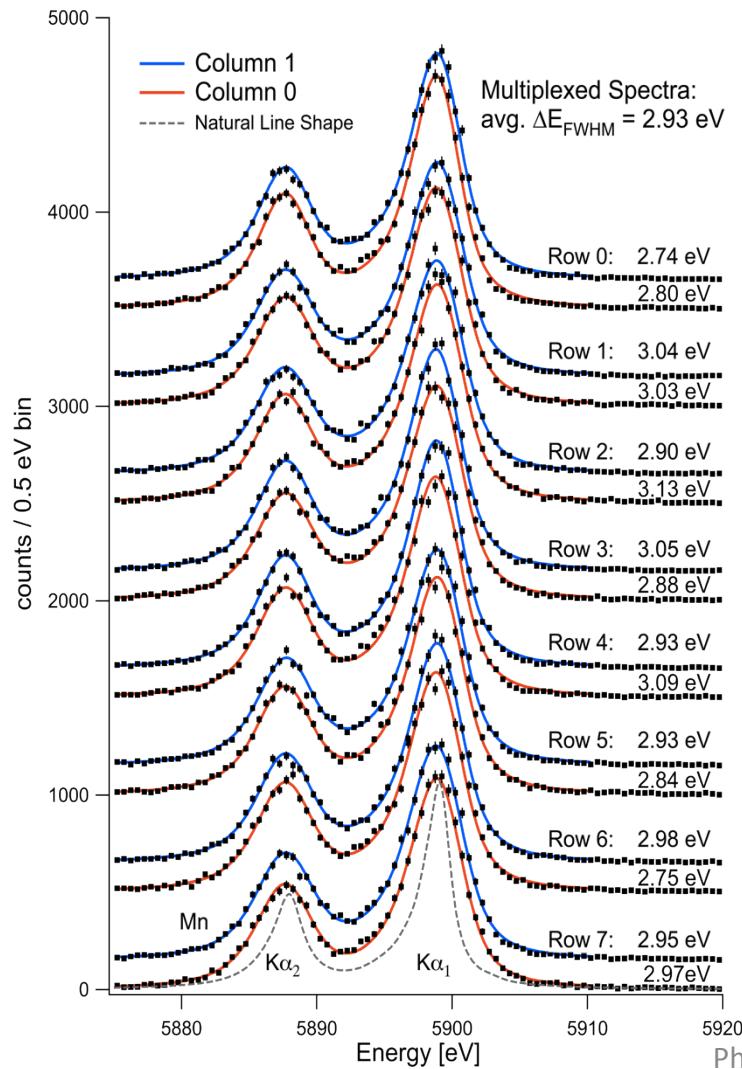
- GSFC / NIST (Kilbourne / Irwin) - reaching higher TRL with new technologies

Very difficult / almost impossible for new small groups to work independently of large facilities. Encourage new University Scientists working together with larger labs. on specific tasks.

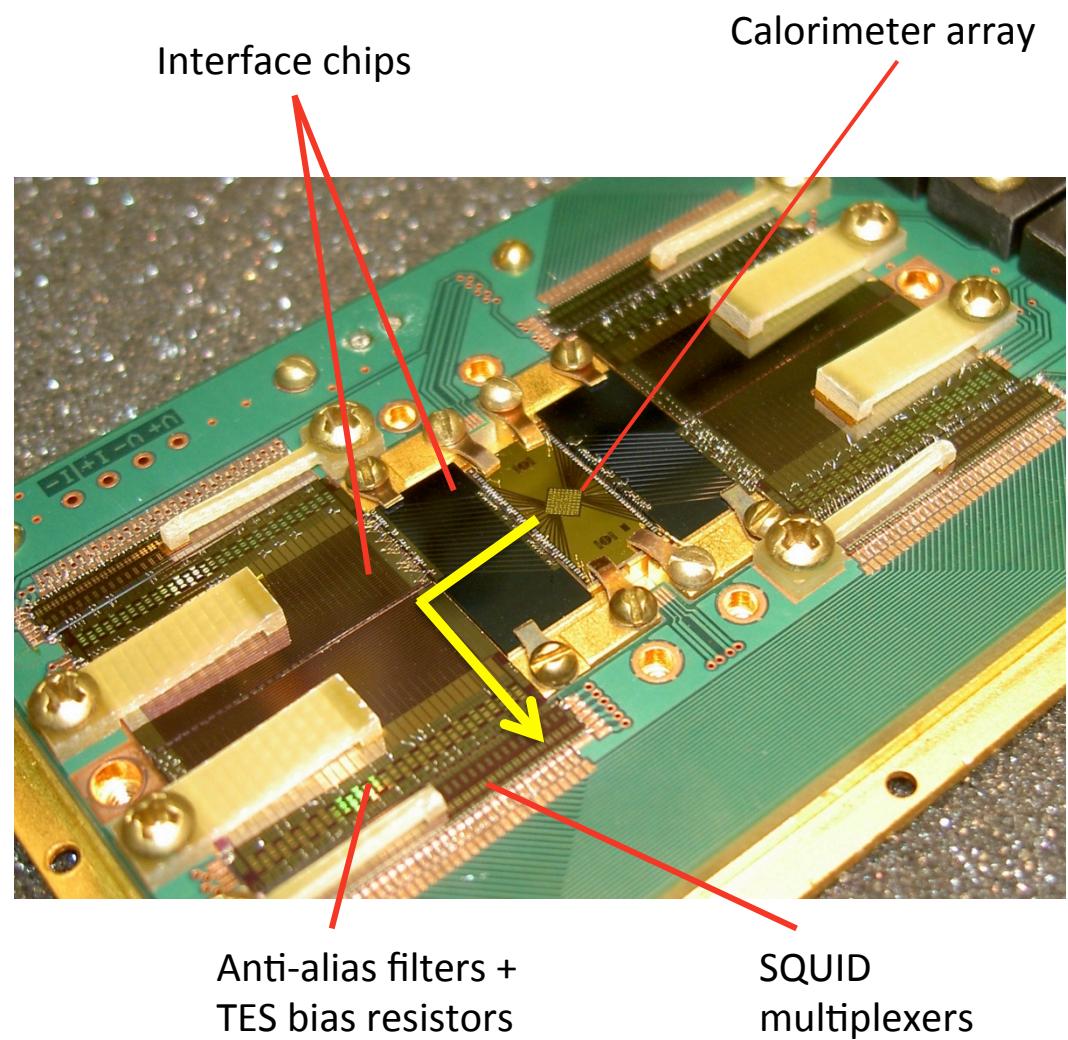
Read-out: Time division multiplexing

2 x 8 mux readout of 8x8 array (250 μm pixel)

$$\Delta E_{\text{FWHM}} = 2.9 \text{ eV}$$



GSFC 8 x 8 array
NIST SQUID MUX readout



Code division multiplexing (CDM):

Reason: Does not have “multiplex disadvantage” that exists for TDM multiplexing

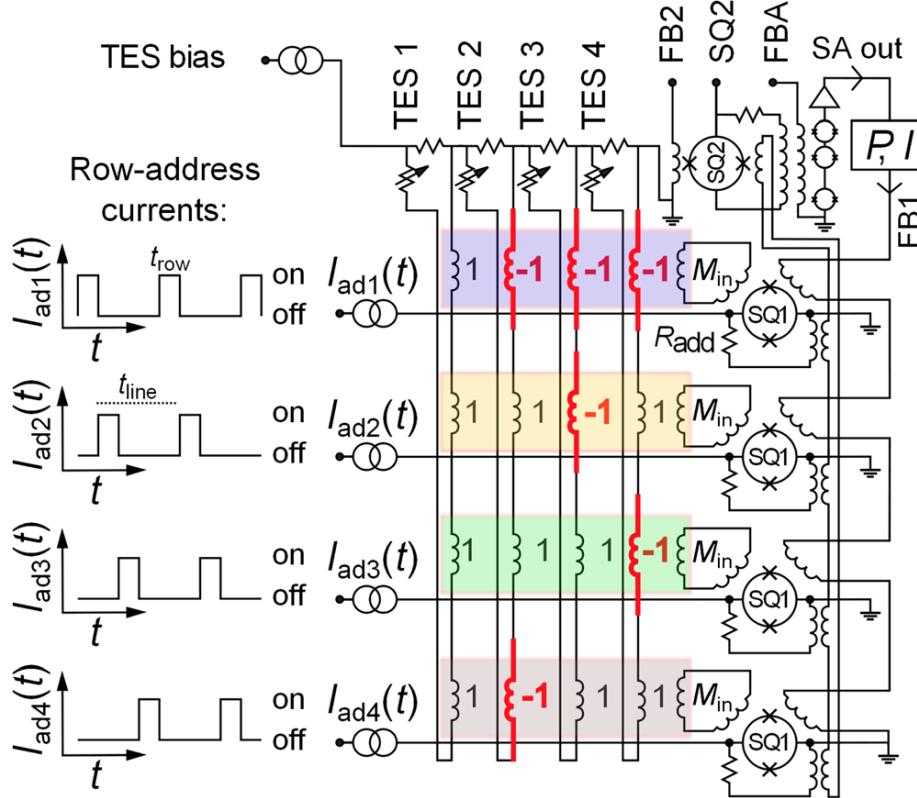
⇒ Better energy resolution / greater engineering margin

How it works:

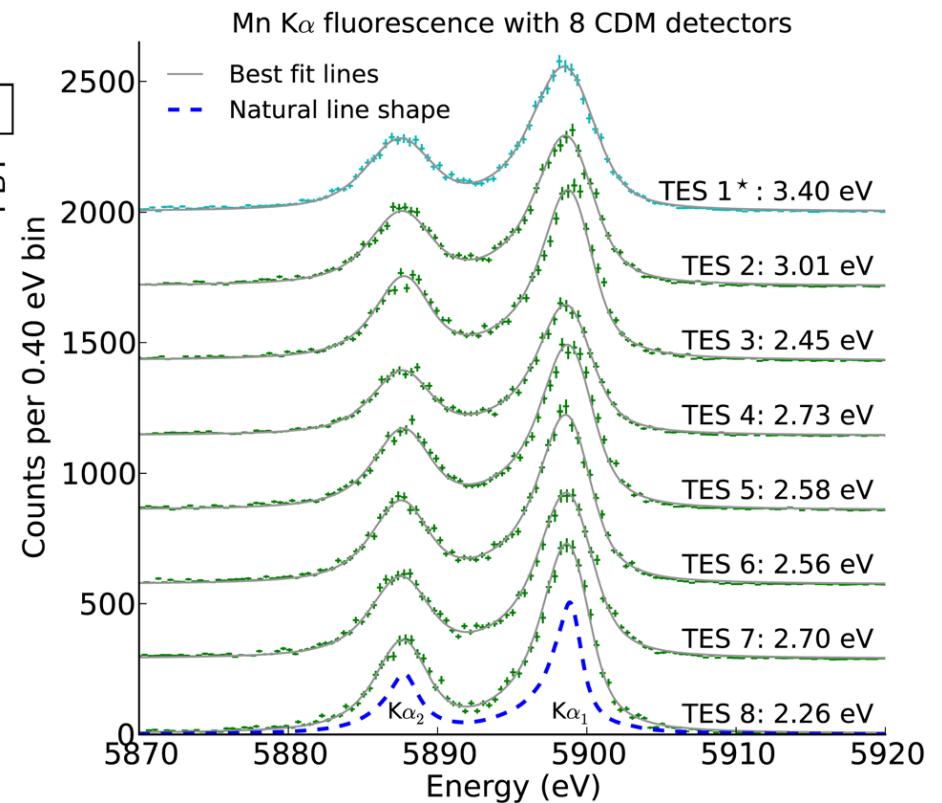
- Every detector pixel is sampled all of the time
- Polarity of coupling to the SQUID switches between +1 and -1 in orthogonal pattern (Walsh matrix)

CDM chips are drop-in compatible with existing 32-row TDM systems but have higher performance.

Circuit (flux coupled CDM):



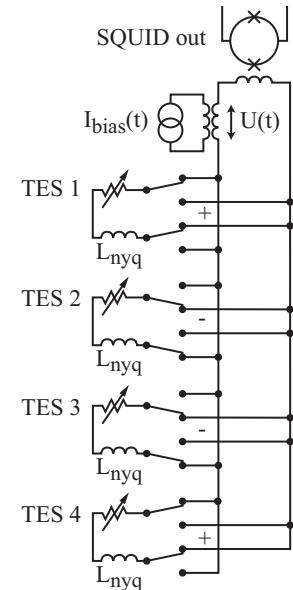
Promising first results from 1x8 CDM demonstration:



Future Multiplexed Read-out Technologies

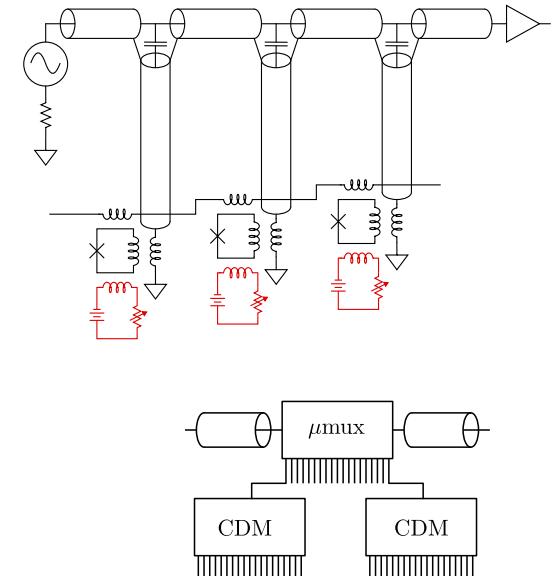
1. Current steering CDM

- Large number of pixels per amplifier
- Fewer wires
- Could lead to 3-D geometries => greater multiplexing
- Being developed first for bolometer applications which require lower currents (easier)



2. Microwave readout

- Longer term
- Again being spear-headed by research for bolometer applications (easier)
- Can be integrated with CDM concepts
- Deciding when it is most efficient to begin a parallel effort for microcalorimeters is key
 - Many similar technical hurdles
 - Some differences, depending upon technology
 - MKIDs vs TESs vs MCCs
- Need for flight qualified electronics and components is tricky
 - Rapidly advancing field



Reference design array layout (IXO/XMS)

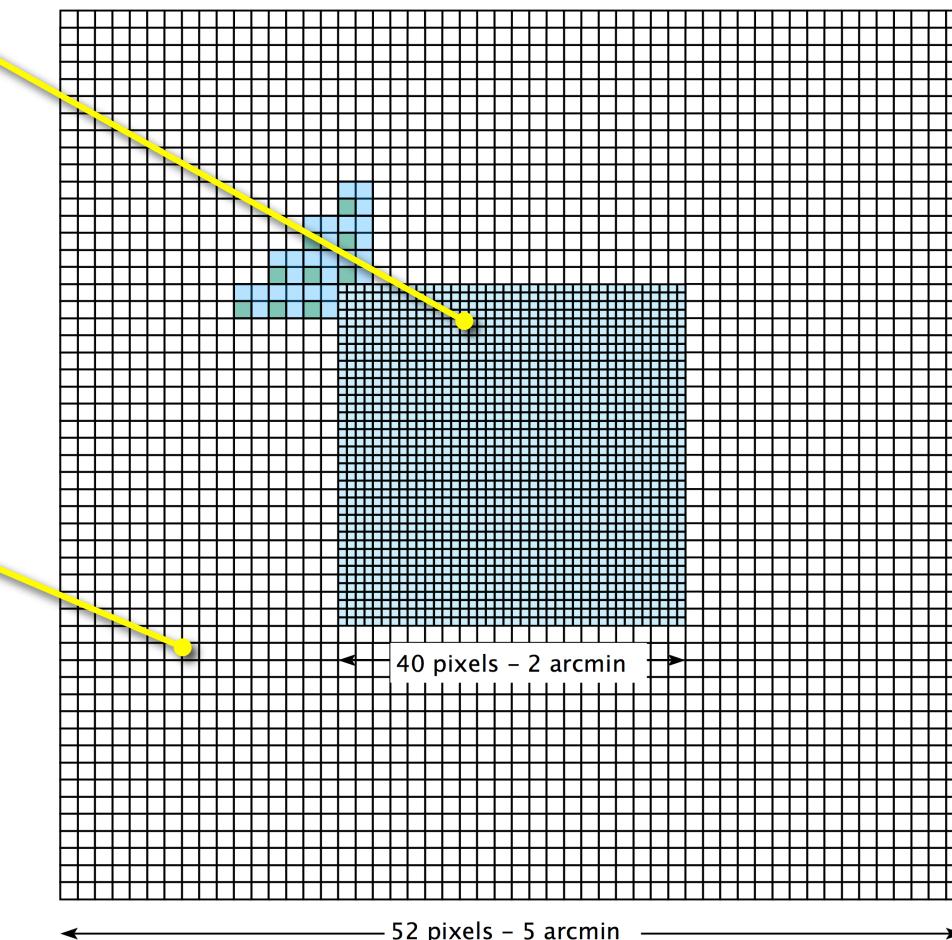


Central, core array:

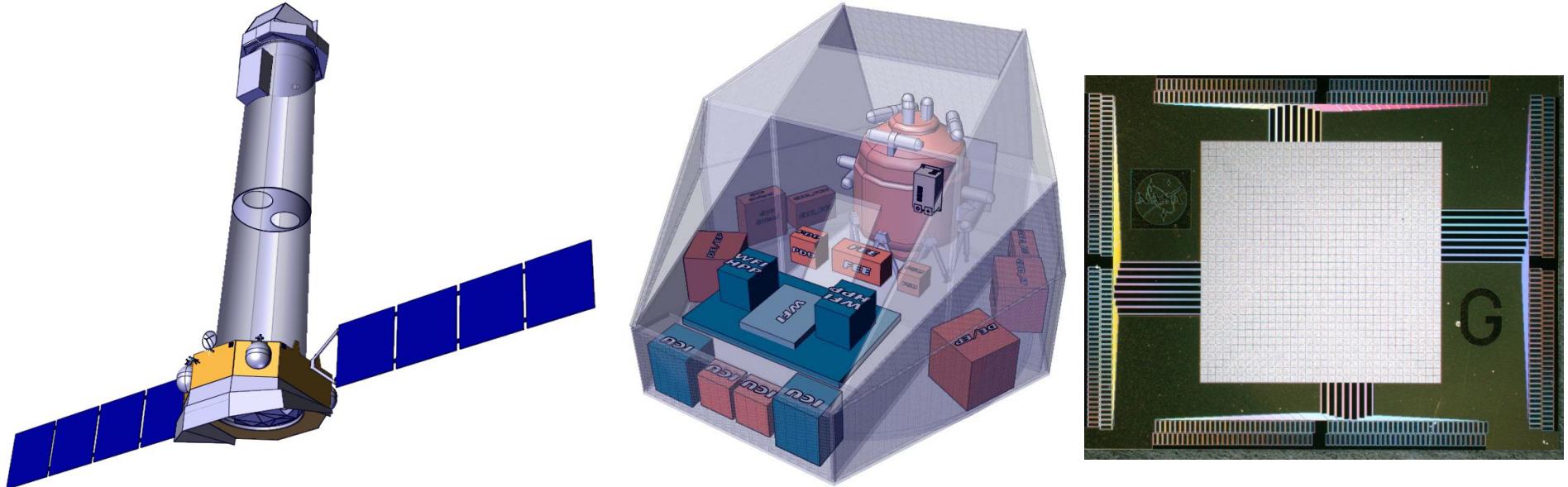
- 40x40 array of Individual TES
 - one absorber/TES
- 2 arcmin FOV
- 2.5 eV resolution (FWHM)
- < 300 μ sec time constant

Outer, extended array

- 4 absorbers/TES
- Extends array to 52 x 52 pixels for a total of 2176 readout channels
- 5.0 arcmin FOV
- < 10 eV resolution
- \sim 2 msec time constant

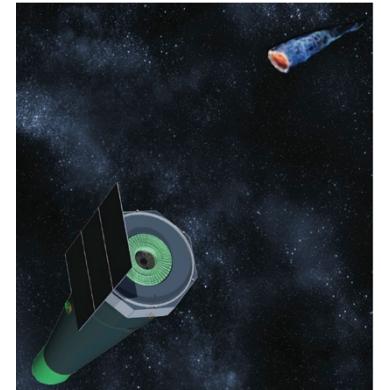


Athena:



Parameter	Old	New	reason
Energy resolution	2.5 eV	3.0 eV	3.0 has been demonstrated on 2 x 8 array
Array size	40 x 40	32 x 32	32 x 32 arrays have been produced (although there is no technical reason the array cannot be larger)
FoV	2 arcmin	2.4 arcmin	Due to shorter focal length, outer array of 5 arcmin dropped
Pixel size	300 µm	250 µm	Good resolution has been demonstrated for 250 µm pixels, due to lower C there is more margin in the error budget
Number of TESs	2176	1028	32 x 32 + 4 anti-co signals, reduces harness significantly as well as
Number of pixels	3904	1028	heat loads in cryostat, no re-design of cryostat (yet)
pixels per channel	32	16	Relaxes cross talk and reduces MUX speed requirements
Regeneration time	< 10 hr	< 3 hr	Regeneration cannot be done during periods when XMS is not in focus, 3 hr feasible for current design

First AXSIO XMS Array Concept

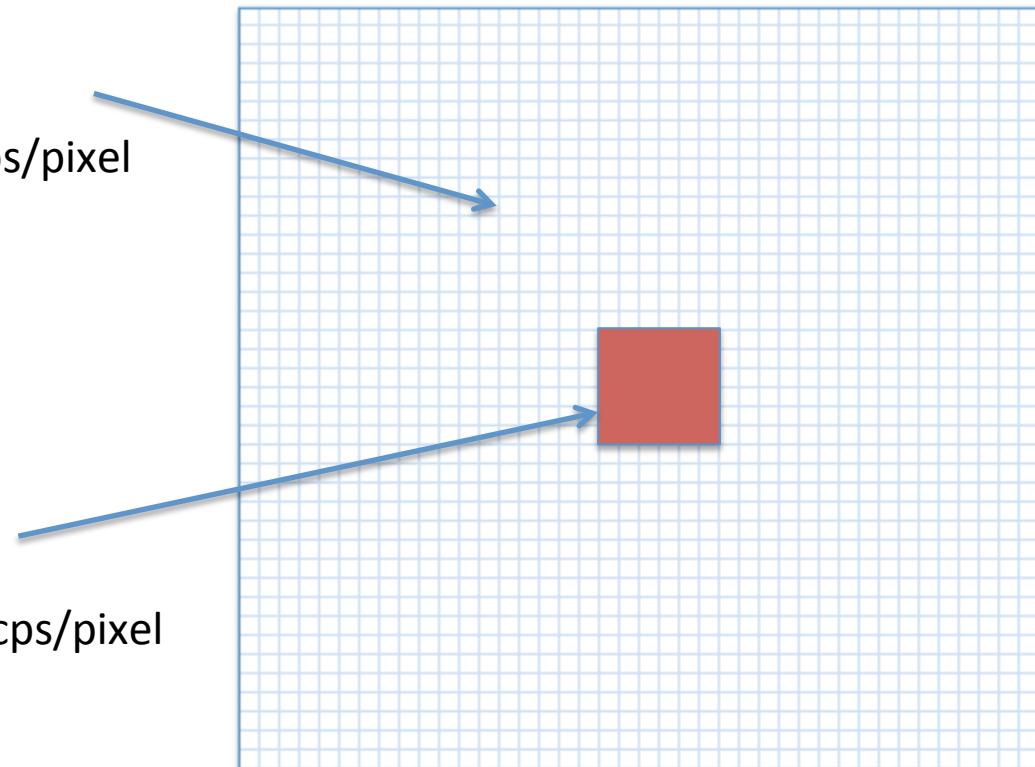


Main array:

- 40 x 40 pixels, 6" each
- 4.0 arcmin FOV
- 300 μm pixels
- 3 eV resolution (FWHM)
- 80% event throughput at 50 cps/pixel

Inner point source array (PSA):

- 24 x 24 pixels, 1.5" each
- 36 arcsec FOV
- 2 eV resolution (FWHM)
- 80% event throughput at 300 cps/pixel

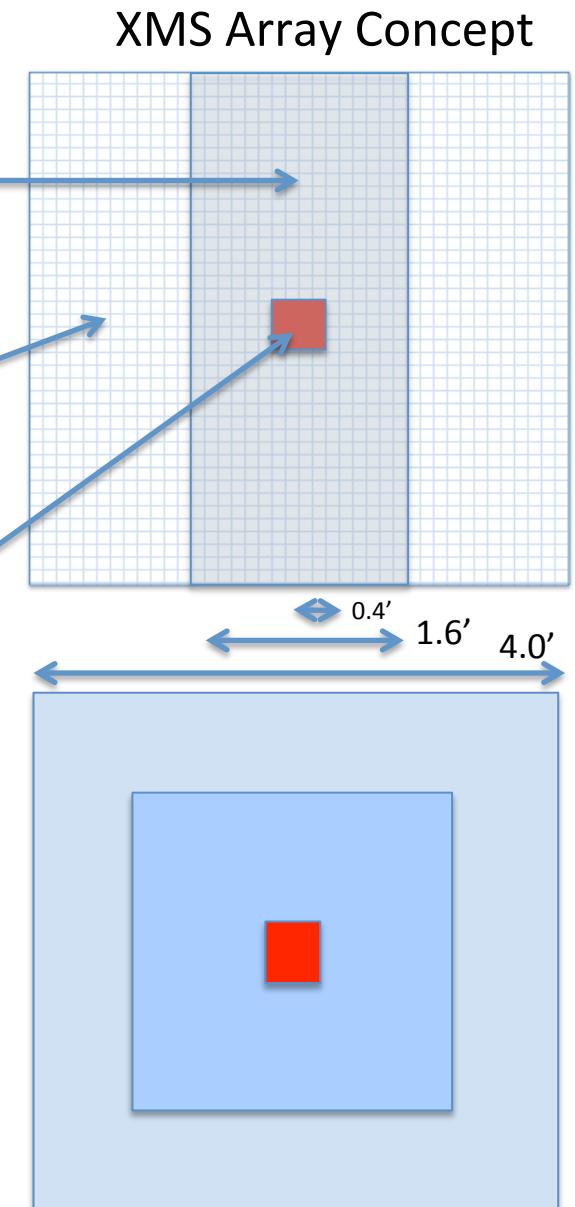


2140 TESs (68 readout columns)
Same as IXO

Streamlined (current) AXSIO concept, “N-Cal” concept

Main array – single silicon carrier chip:

- 40 x 40 pixels, hole in middle: 4 x 4 pixels
- Pixels: 6" each, 300 μm
- 4.0 arcmin FOV
- Shaded region:
 - 16x40 – single pixels
 - < 3 eV resolution (FWHM)
 - 50 cps capability, 80% throughput
 - 624 TESs
- Outer envelope – 4x4 Hydra
 - < 6 eV resolution (FWHM)
 - 10 cps per pixel capability 80% throughput
 - 240 TESs (6x40 each side)



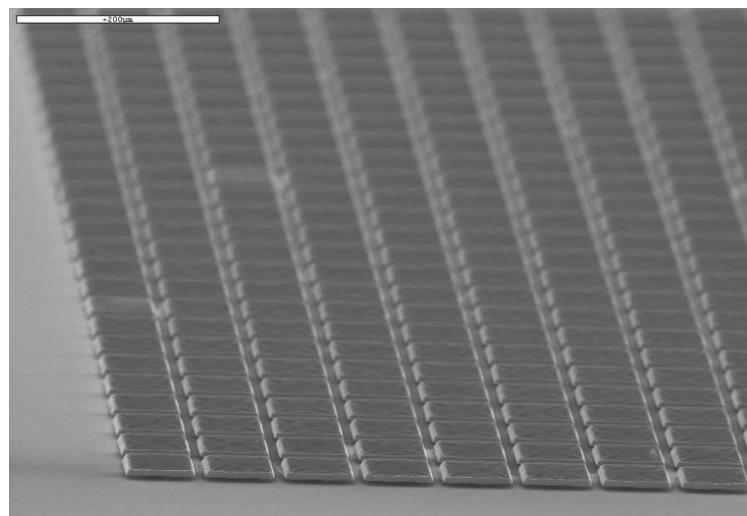
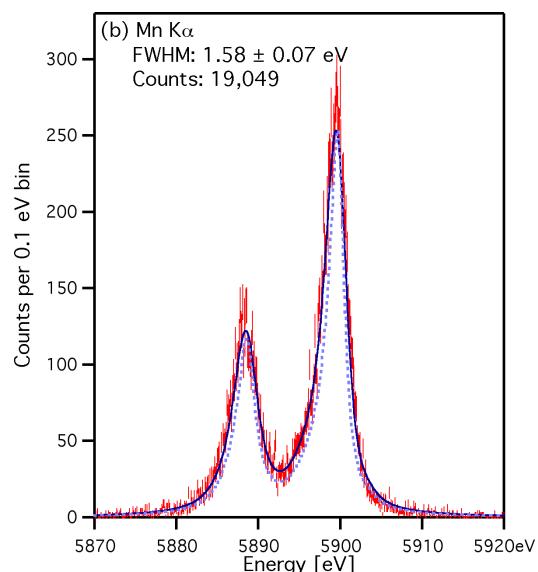
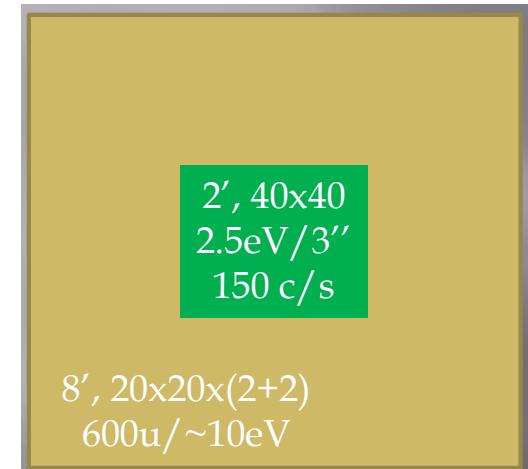
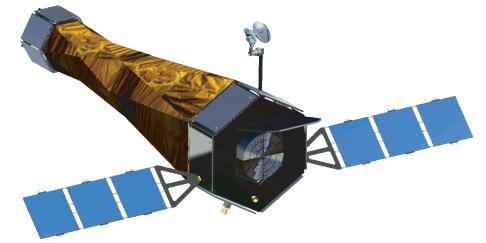
Point source array (PSA):

- 16 x 16 pixels, 1.5" each, 75 μm
- 24 arcsec FOV
- 2 eV resolution (FWHM)
- 80% event throughput at 300 cps/pixel
- 256 TESs

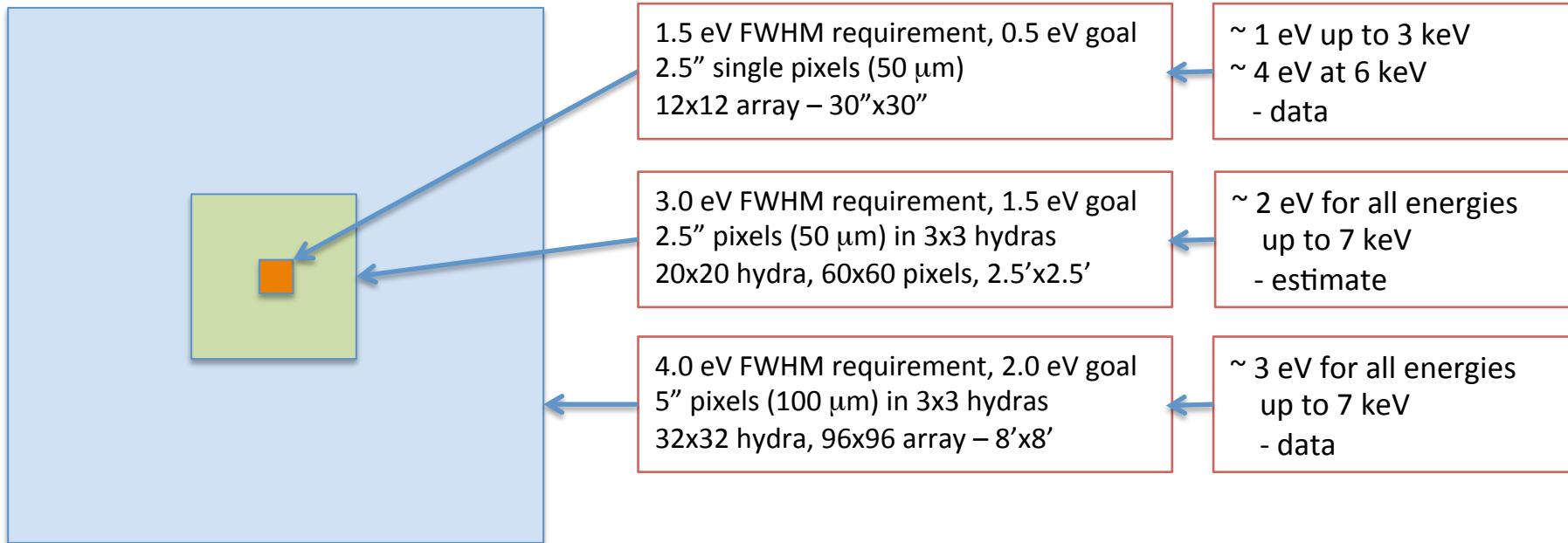
Total = 1120 TESs

The Extreme Physics Explorer - Mike Garcia et al.

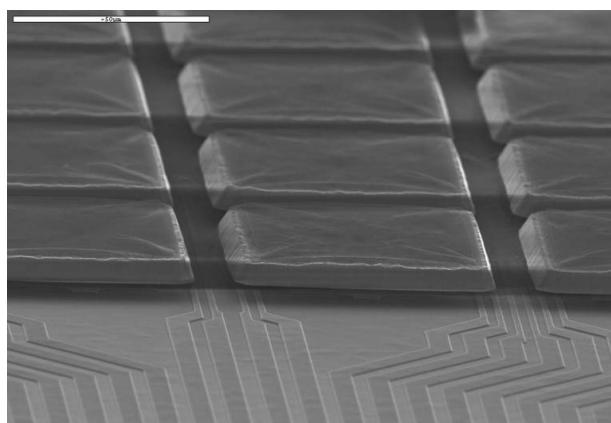
- 10 m focal length (40 m)
- Inner array:
 - 40x40 array of high count-rate pixels (150 cps)
 - Angular resolution $\sim 1'$, $2'$ FOV
 - 3'' pixels - over-sampling point spread function
 - 150 um pitch, 145 um x 145 um x 4.5 um pixels
 - (or 600 um x 600 um pixels)
 - $\Delta E < 2.5$ eV [FWHM]
- Outer array:
 - 20x20 TESs, each 2x2 Hydra
 - 8' FOV, 12'' pixels
 - 600 um pitch between absorbers
 - $\Delta E < 10$ eV [FWHM]
 - Old IXO outer array hydra design



“Sahara” - Spectral Analysis with High Angular Resolution Astronomy - (Mushotzky et al.)



Shorter focal length => Small pixels
+ high angular resolution



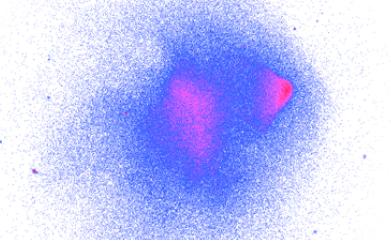
4 m focal length, small pixels
Local length: 4m
Angular resolution: 5"
FOV: 8' x8'

Different design types in different regions
on a single wafer substrate

12k pixels, with only 1344 TESs read-out !

SMART-X

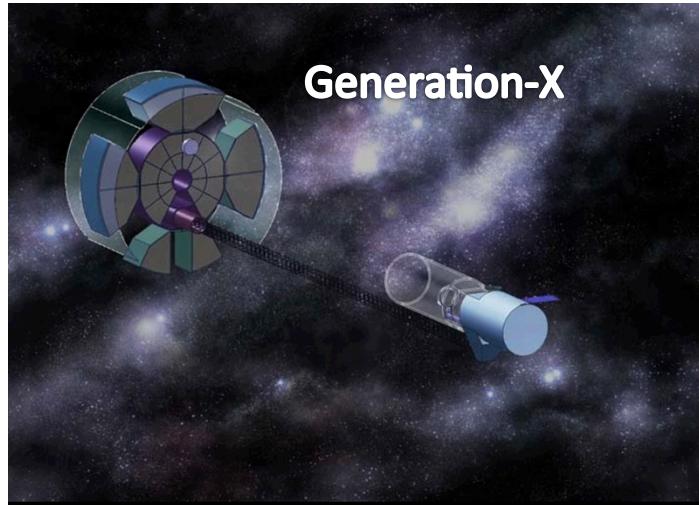
“Square Meter, Arcsecond Resolution X-ray Telescope”



- 2.3 m² effective area, 10 m FL, 0.5" angular resolution X-ray telescope
- 5' FOV, 1" pixel size microcalorimeter

Microcalorimeter:

- 5' x 5'
- 50 μm (1") pixels - *90k pixels !*
- < 5 eV energy resolution
- 4x4 or 5x5 Hydras
- Max. 20 cps/TES count-rate capability
- Multiplex 64-128 TESs (CDM multiplexing assumed)
- Same number of read-out channels as AXSIO !



*Observatory with 100 m² Effective Area
and 0.1" angular resolution*

For the 60 m focal length,
0.1" pixels => 30 μm pixels

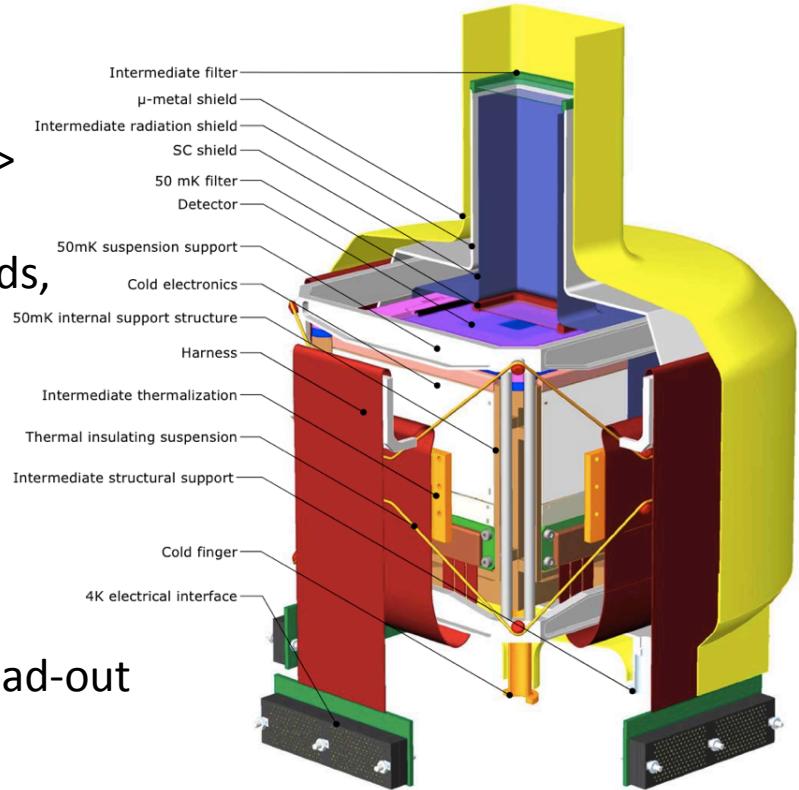
3'x3' => 1800x1800 array of 0.1" pixels
=> **3.24 x 10⁶ pixels**

- 324,000 position sensitive calorimeters
- 3x3, 2x5, 4x4 Hydras (10 absorbers per TES previously assumed)
- Microwave multiplexing of SQUIDs
- 8 HEMT amplifiers
- Just ~ 24 coax cables
- 1265 RF SQUIDs multiplexed on each HEMT amplifier
- Code division multiplexing – 32 TESs per SQUID readout

Distant future????

What limits number of pixels?

1. Number of amplifier channels (MUXed read-out) -> electronics cost & power
2. Size / mass of FPA - ability to withstand launch loads, magnetic shielding
3. Easy attachment of pixels within plausible size (wire-bonding) -> bump-bonding etc.
4. Number of stripline wires between pixels
- in planar geometries (goes as $n/4$ for $n \times n$ array)
5. Complexity of wire routing through connections
6. Thermal management of power from pixels and read-out
7. Use of Hydras etc.
8. Count rate requirement

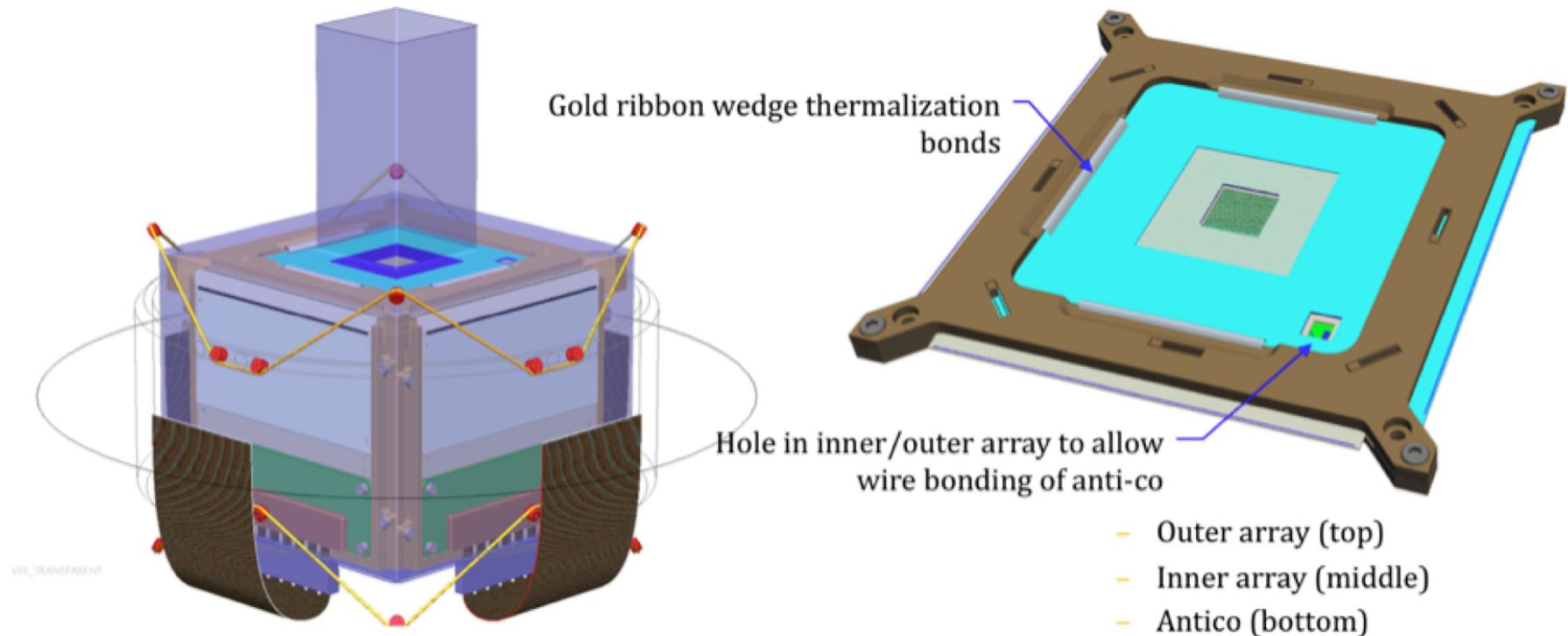


50 mK focal
plane assembly

Somewhere between 1k - 100k pixels with technology under development, depending on details of what is required.

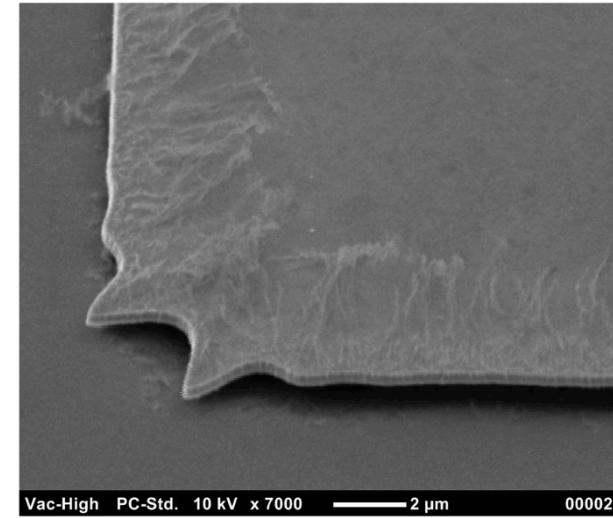
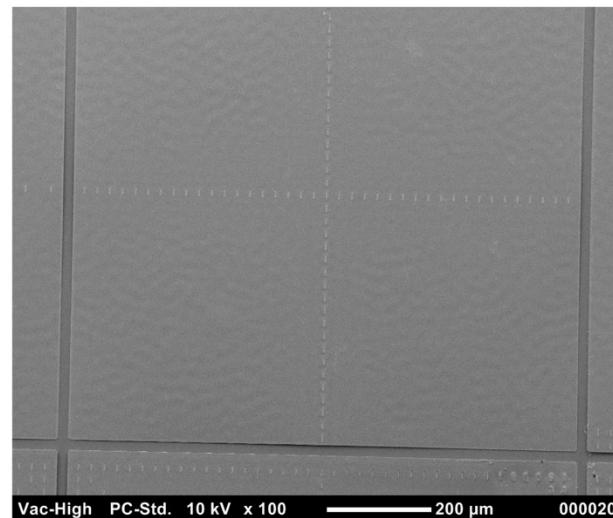
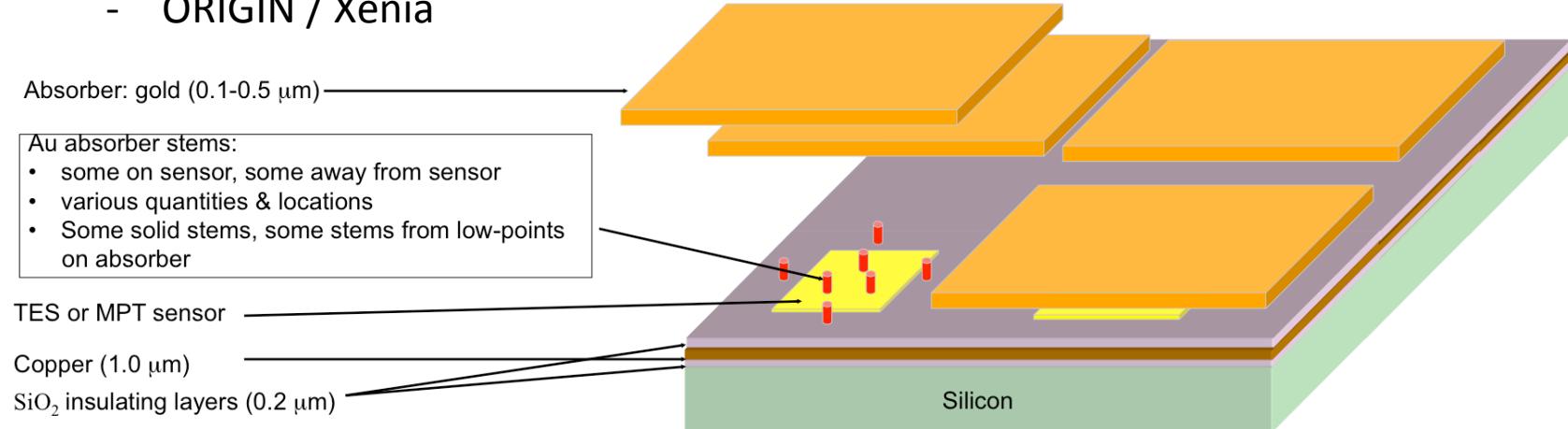
TRL6 : Integrated detector system

- Multiplexed (6x32) read-out of portion of full composite focal plane array
 - 128 different single-TES pixels in a 40x40 core array
 - 64 multi-absorber TES (256 0.6-mm pixels) of a full-sized outer array
 - Particle-veto integrated into the test set-up
- Electrical and thermal interconnects and staging approach flight-worthy design



Working towards 1 mm x 1 mm pixels with ~ 1 eV energy resolution up to 1 keV

- XQC
- DIOS
- ORIGIN / Xenia



Getting to TRL-6 vs. new capabilities

Where to put the emphasis - size/ count rate ?

- 250-300 um pixels ?
 - bismuth
 - membranes
- Smaller pixels / Hydras - where calorimeters "work" better ?
- Larger pixels 1mmx1mm and above, ~ 1eV res. – WHIM ?
- Read-out ?
- FPA TRL ?
- Moving towards < 1eV ?
- Highest count-rates ?

What array size should we me aiming for ?

Astro-H 36 pixels => 1kor 4k or 10k or 100 k ?

We welcome your feedback on emphasis !

Conclusions

- Developing/optimizing a variety of pixel designs for future microcalorimeter array types
 - Ground-breaking performance; steady, consistent progress
 - New detector ideas regularly developed
 - Increasing TRL of existing technologies
 - Moving towards larger arrays
- Thank you X-ray community
 - Microcalorimeter scientists fortunate to have had consistent funding for a large number of years
 - Has maintained well-defined goals to justify development programs
- Strong teams of X-ray Microcalorimeter technologists supported in the US
 - Strong scientific teams built by Rich Kelley, Caroline Kilbourne, Kent Irwin, Scott Porter and many others
 - Consistently lead the world in majority of the key areas
 - Responsive to new opportunities to work with X-ray scientists throughout the US
 - Embrace opportunities for international collaboration, as desired by X-ray community



Let's build a mission !